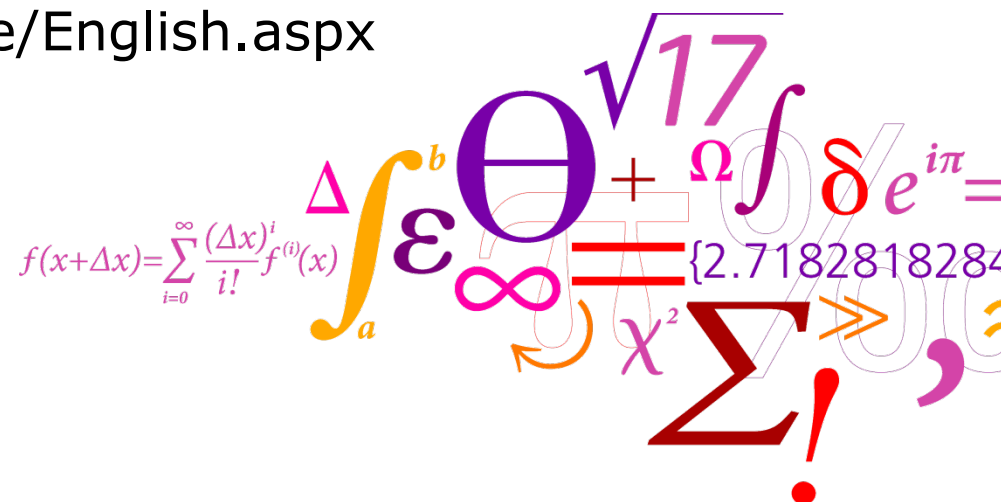


PwrSoC enabling architectures in different applications

Arnold Knott

DTU Elektro, Electronics Group
 Technical University of Denmark,
 akn@elektro.dtu.dk

<http://www.dtu.dk/centre/ele/English.aspx>



DTU Electrical Engineering
 Department of Electrical Engineering

Applications for PwrSoC
Enablers: semiconductors
Disablers: passive components
What's new on the architecture side?

AGENDA

Applications for PwrSoC

Enablers: semiconductors

Disablers: passive components

What's new on the architecture side?

AGENDA

Popular applications

- Chargers

(<http://www.folomojo.com/ces-2015-beyond-smartphones-mind-blowing-new-devices-revealed/>)

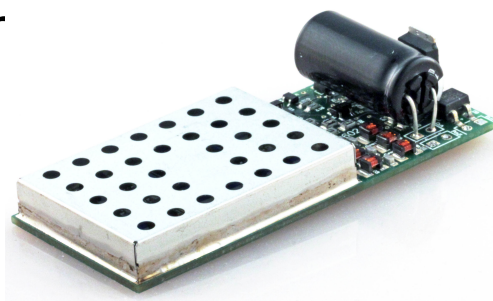


- Point of load

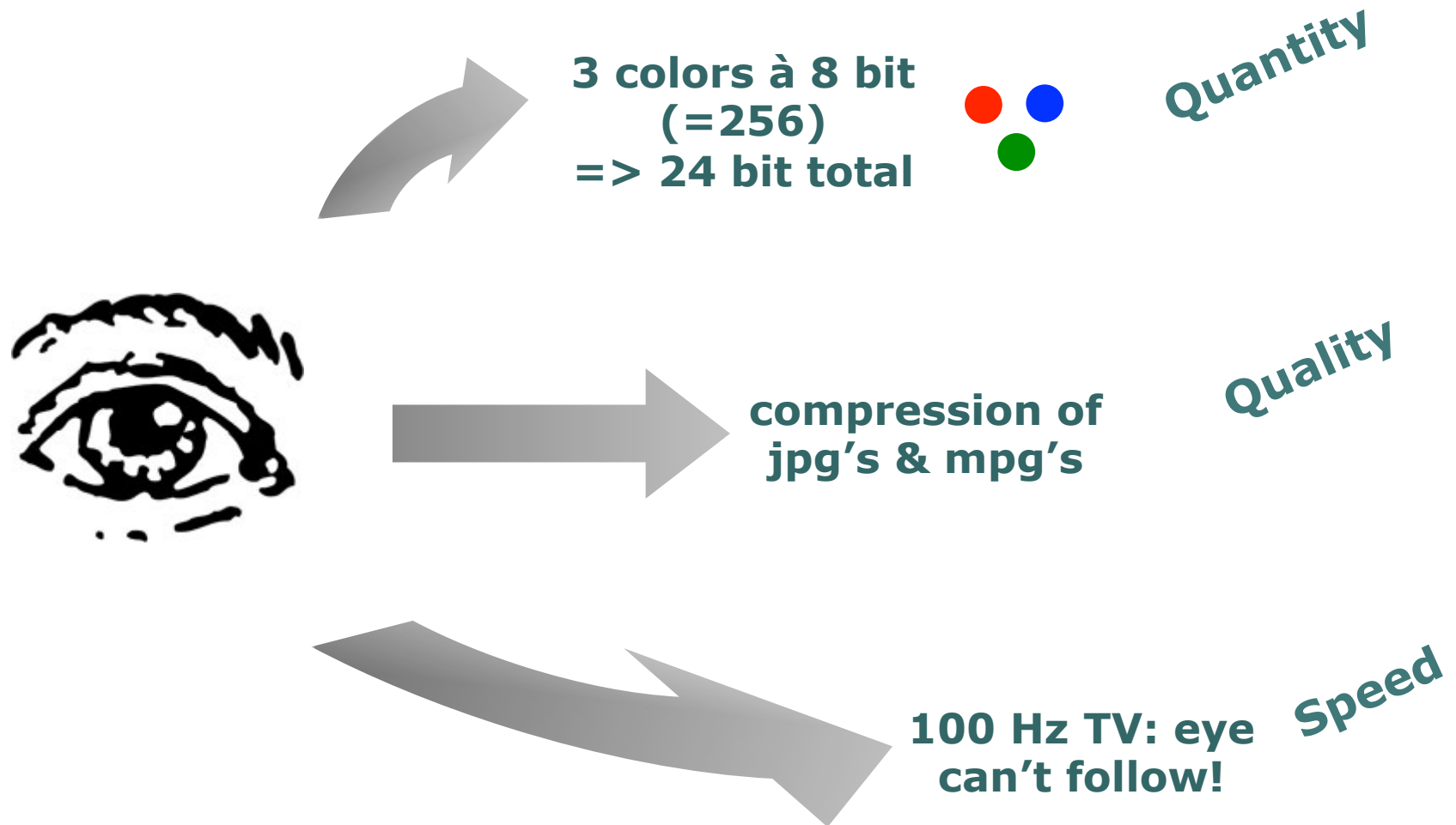
(Integrated Power Delivery for High Performance Server Based Microprocessors, J. Ted DiBene II, PowerSoC08)



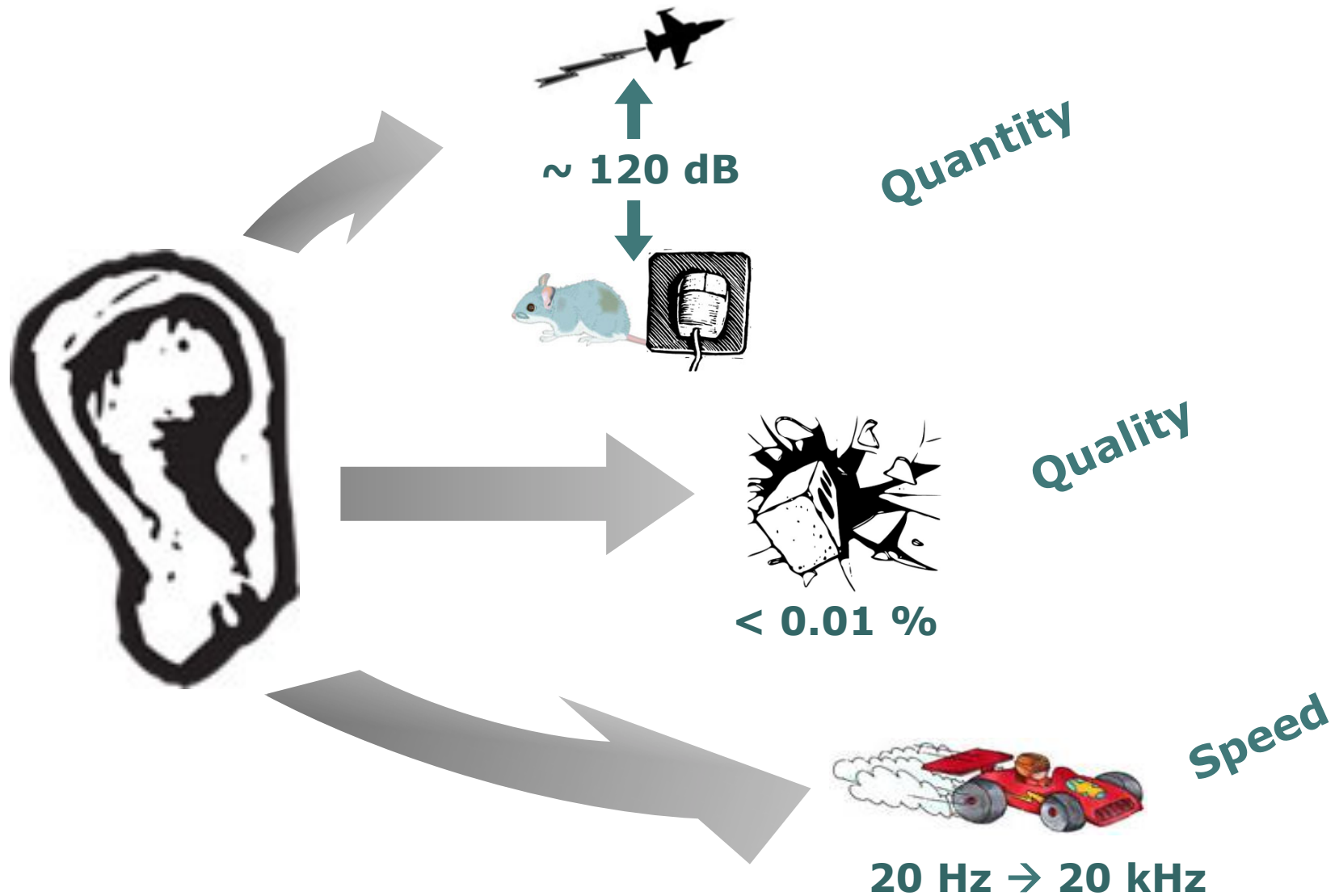
- LED driver



LED drivers

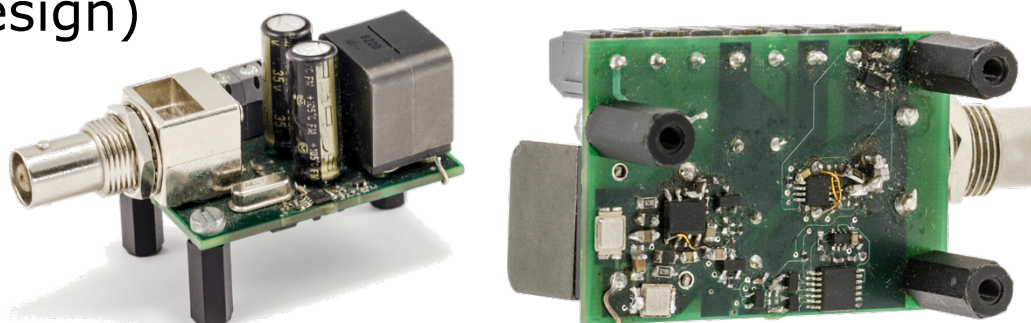


So, what's different in audio applications?



Today's audio power amplifiers

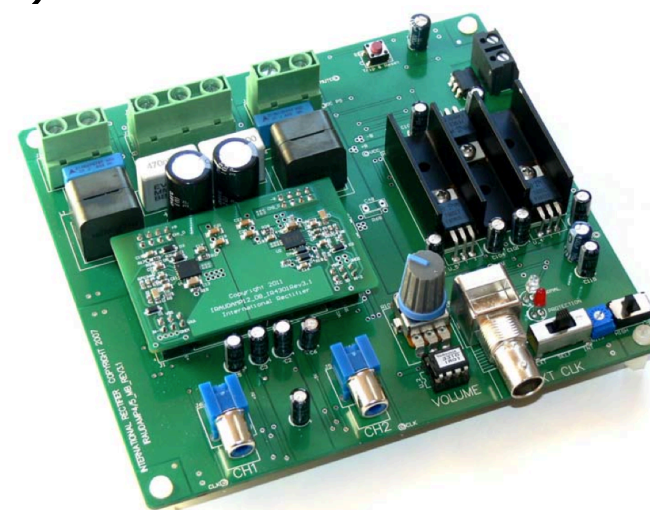
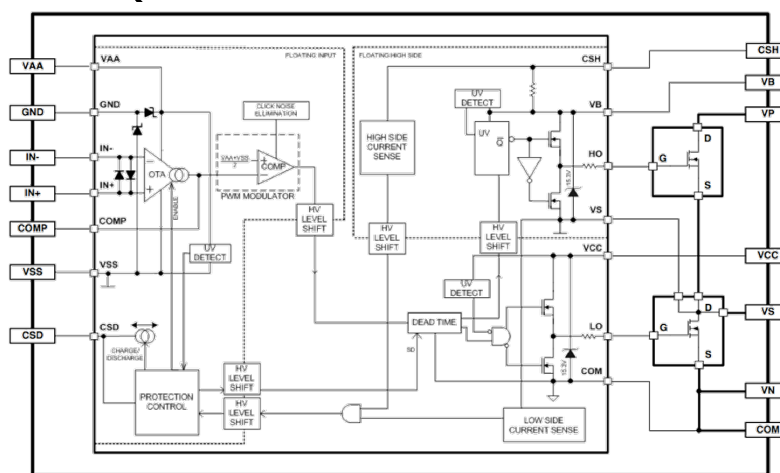
- 100 W (discrete design)



- 90 W / 135 W (IR4321M in IRAUDAMP21)



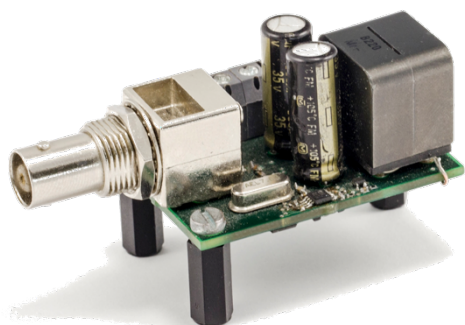
5 x 6 mm²
PQFN22



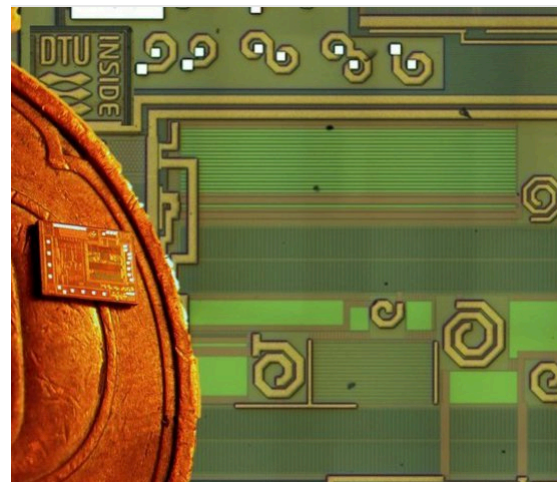
- Similar examples from TI, NXP, ST and others

My research goal

- Fully integrated audio power amplifier with high efficiency...



... and any other power application in DC/AC, AC/DC, DC/DC



Applications for PwrSoC

Enablers: semiconductors

Disablers: passive components

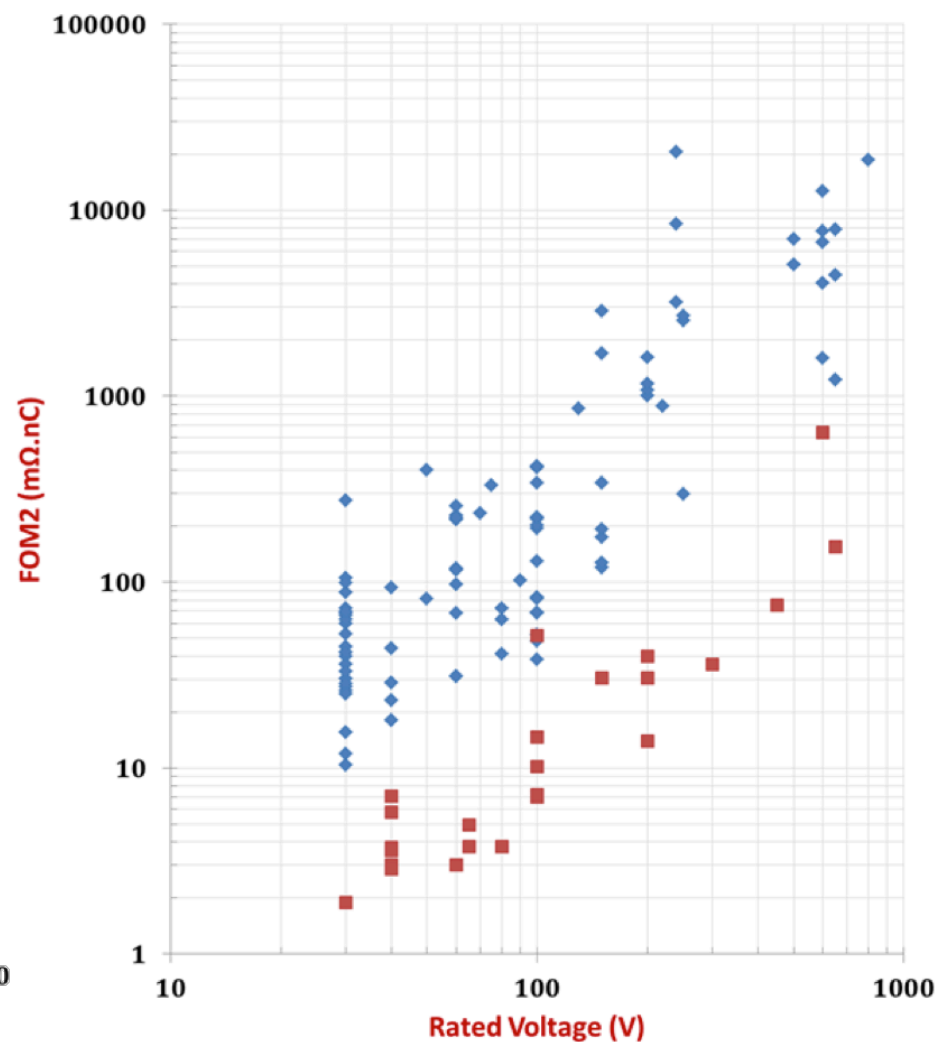
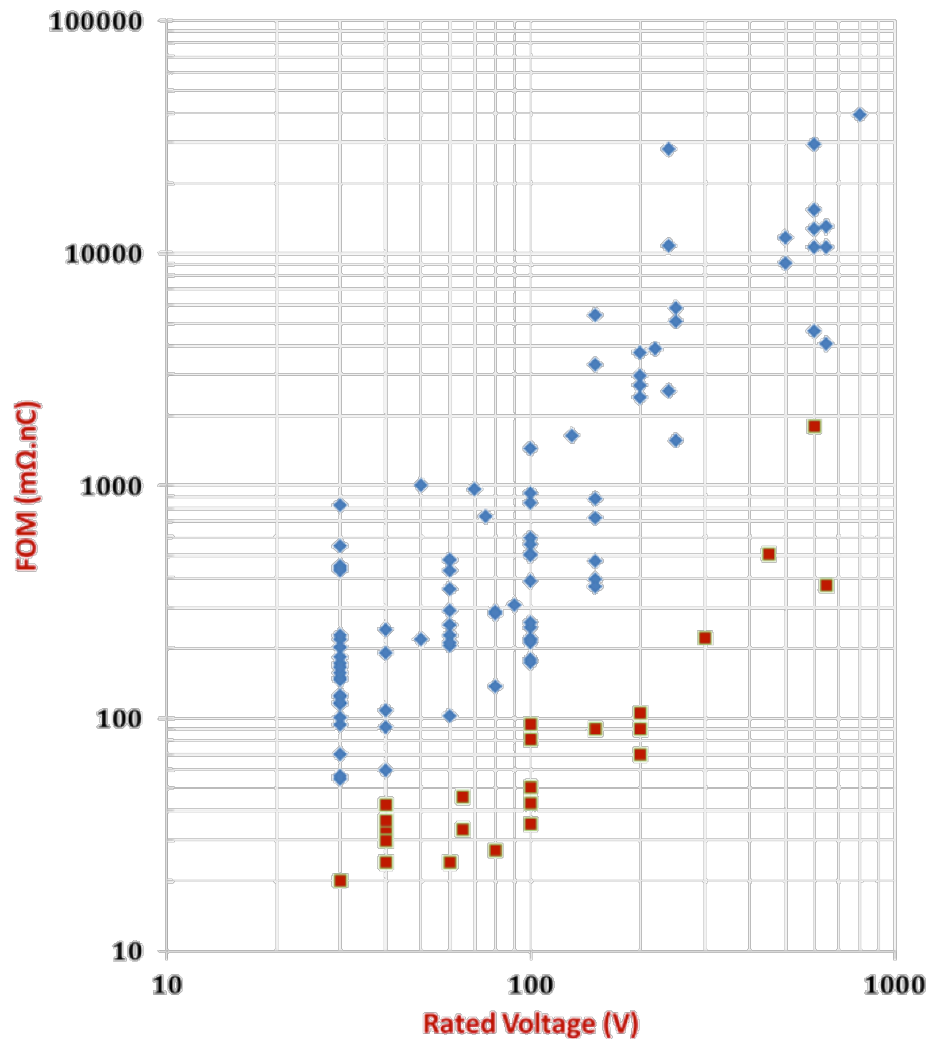
What's new on the architecture side

AGENDA

FOMs on input of GaN & Si

$$\text{FOM} = Q_g \times R_{ds} \text{ (m}\Omega\cdot\text{nC)}$$

$$\text{FOM2} = Q_{gd} \times R_{ds} \text{ (m}\Omega\cdot\text{nC)}$$



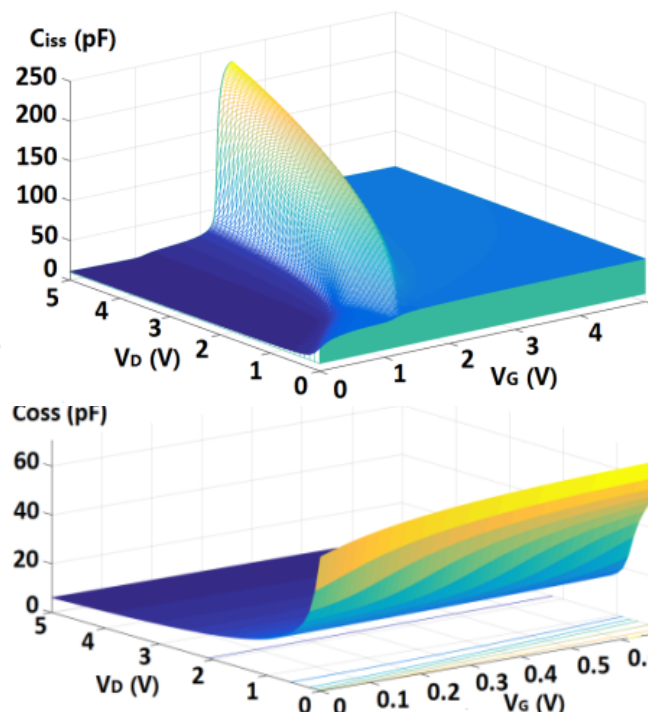
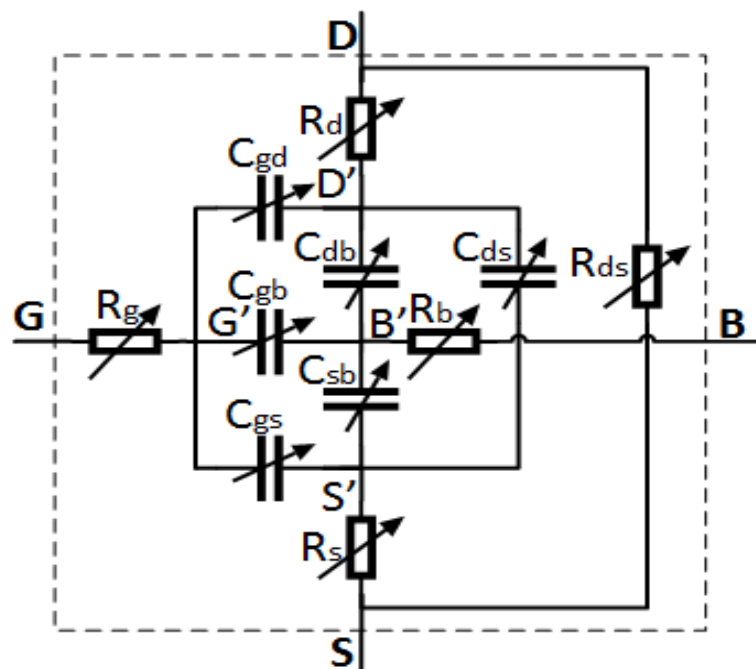
◆ Si MOSFETs - Discrete

■ GaN FETs - Discrete

◆ Silicon MOSFETs - Discrete

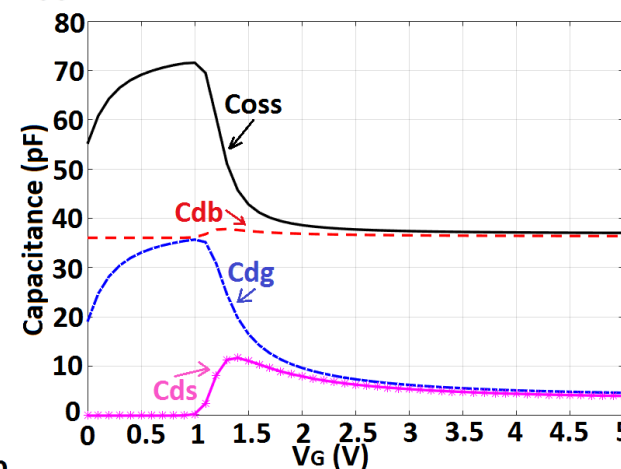
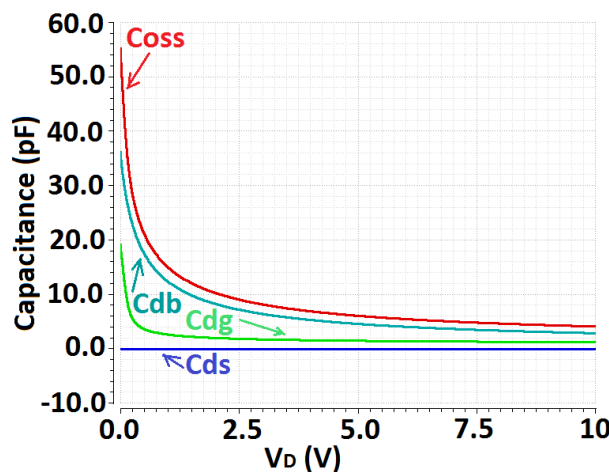
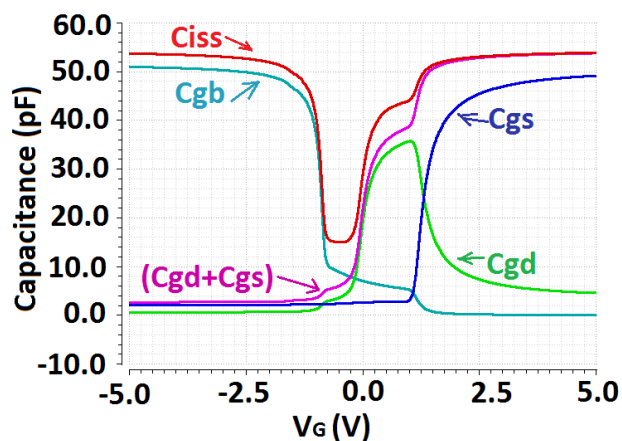
■ GaN FETs - Discrete

Nonlinear capacitance modeling

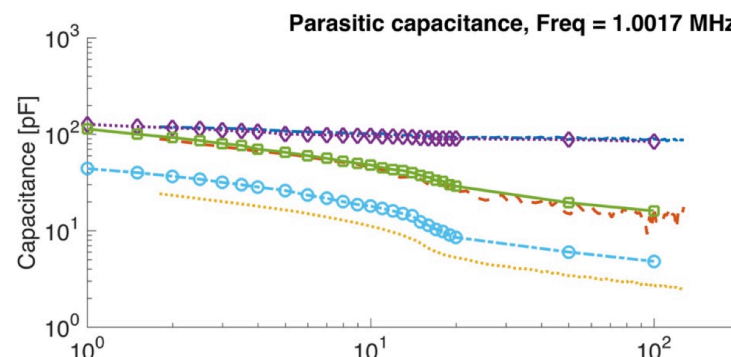
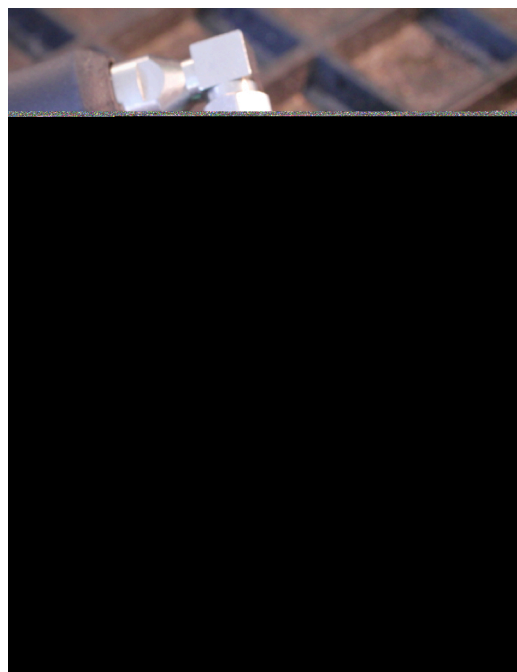


E-poster tomorrow!

Fan L., et. Al, "Nonlinear Parasitic Capacitance Modelling of High Voltage Power MOSFETs in Partial SOI Process." *Elektronika ir Elektrotechnika* 22.3 (2016): 37-43.

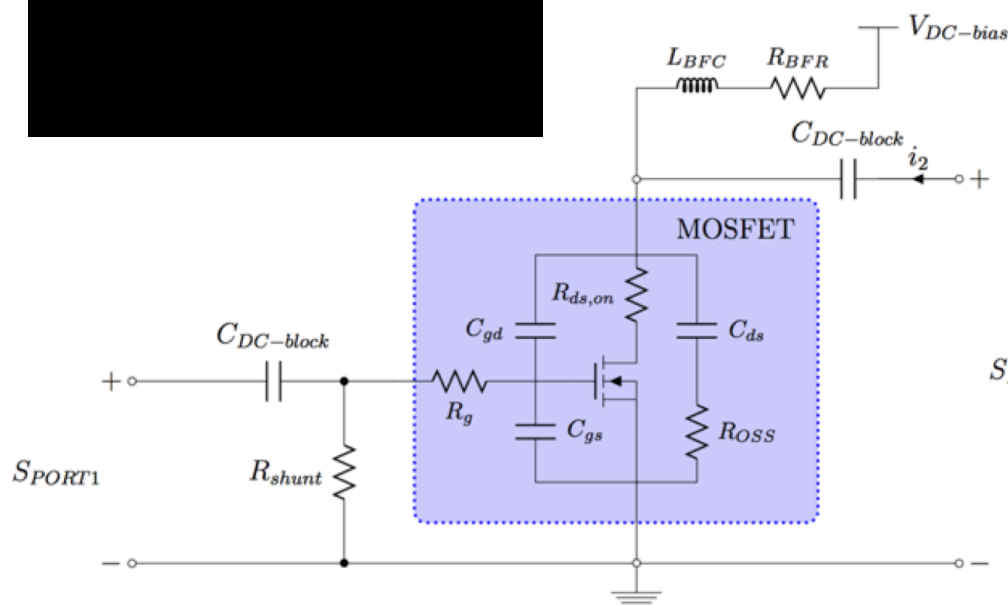
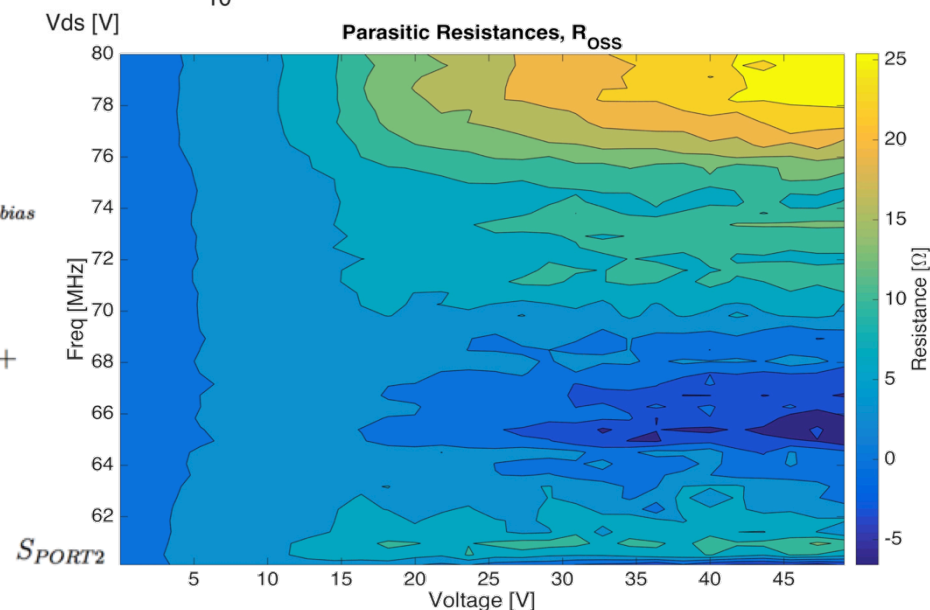


Modeling of losses in C_{oss}



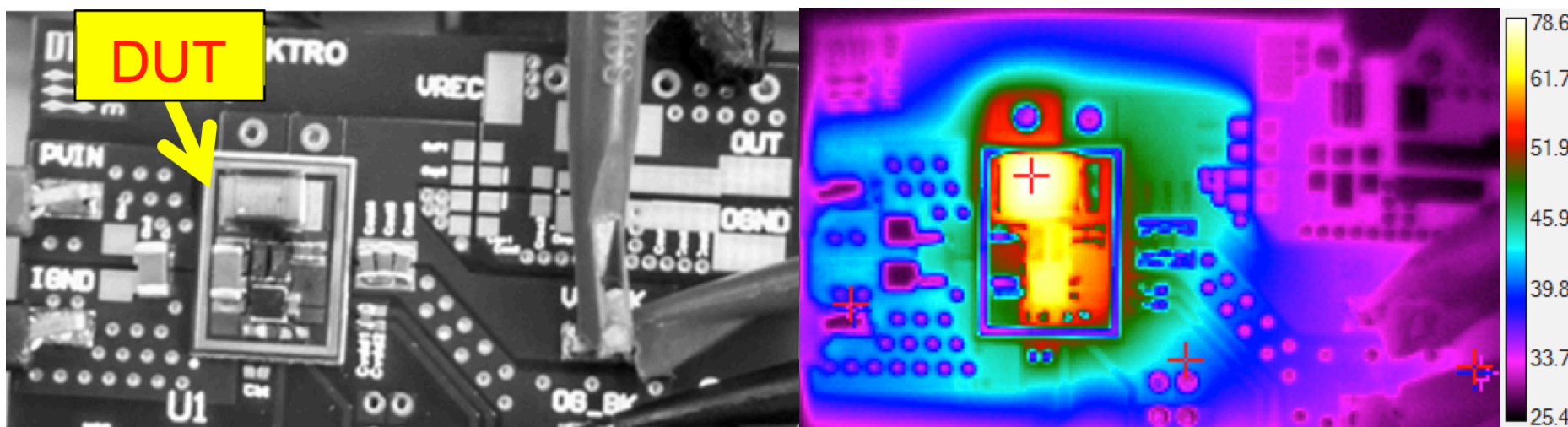
--- Ciss
 --- Coss
 --- Crss
 --- Ciss_{datasheet}
 --- Coss_{datasheet}
 --- Crss_{datasheet}

E-poster tomorrow!



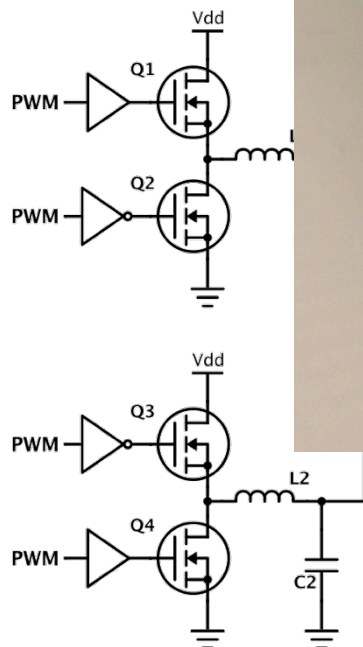
Discrete GaN design

- $V_{in} = 40 \text{ V}$, $V_{out} = 10 \text{ V}$
- $P_{out} = 12 \text{ W}$
- $\eta_{peak} = 87 \%$
- $P/Vol = 20 \text{ W/cm}^3$
- More to come at APEC!

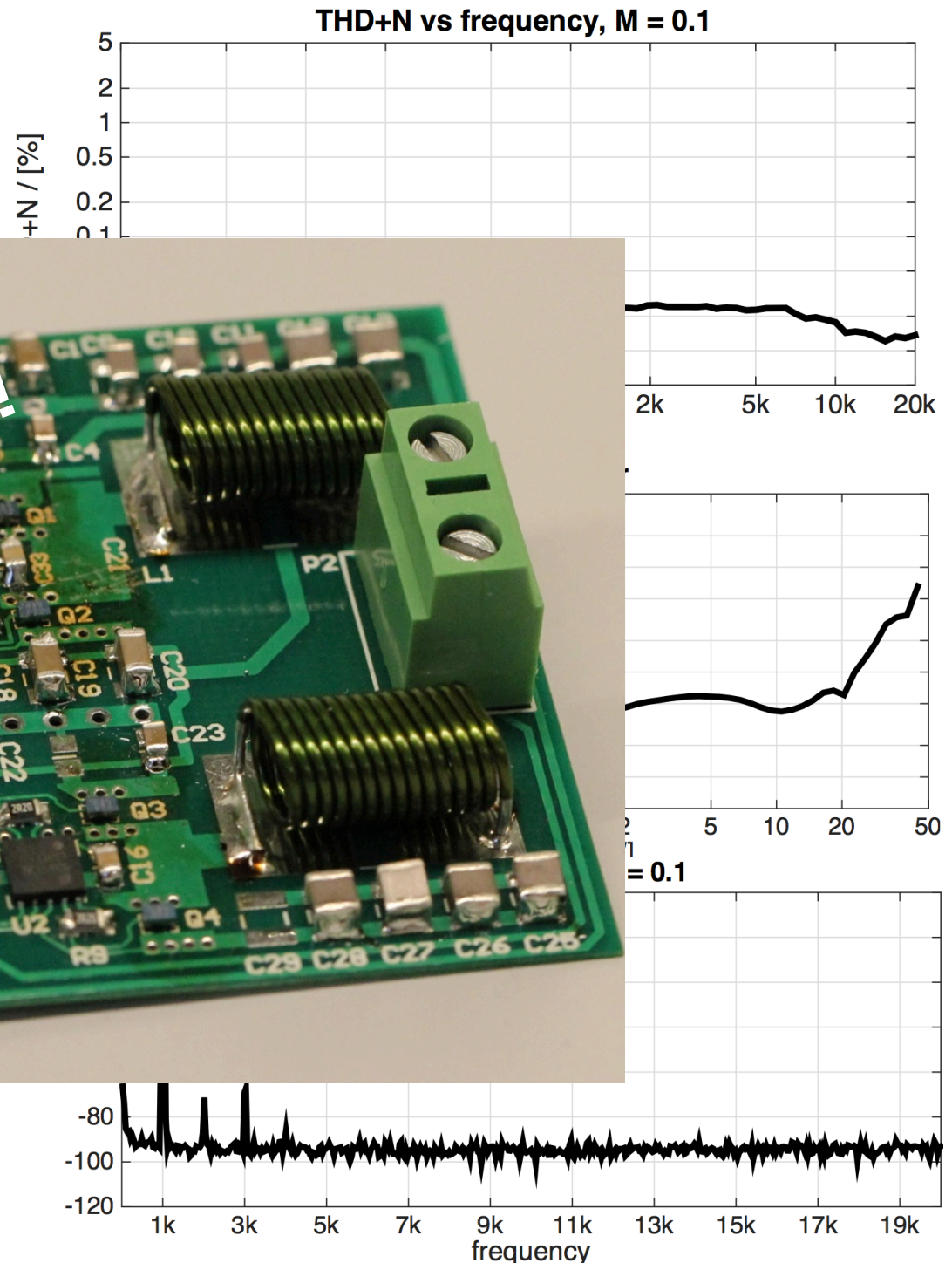


GaN-based audio power amplifiers

- $V_{in} = 40$
- $f_{sw} = 1$ M
- $P_{out} = 50$
- EPC2016



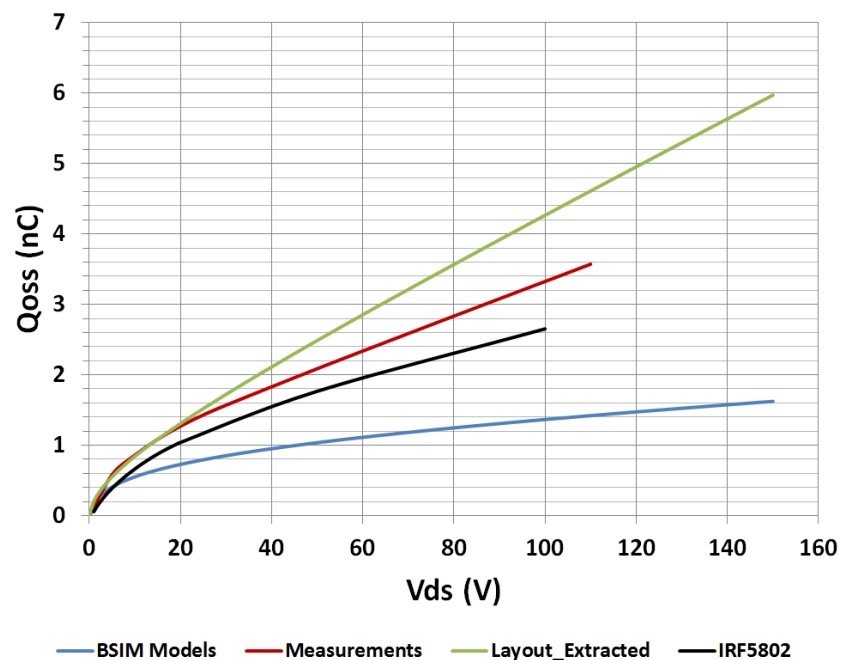
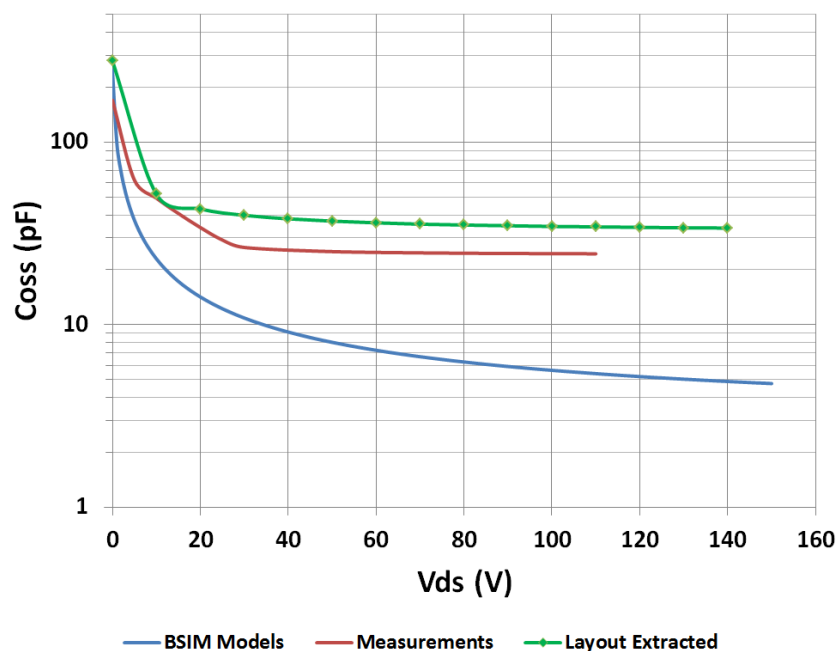
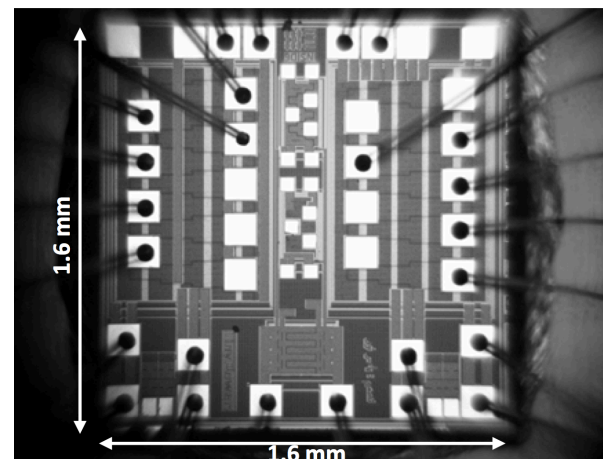
Amplification." Audio Engineering Society Convention 138. Audio Engineering Society, 2015.

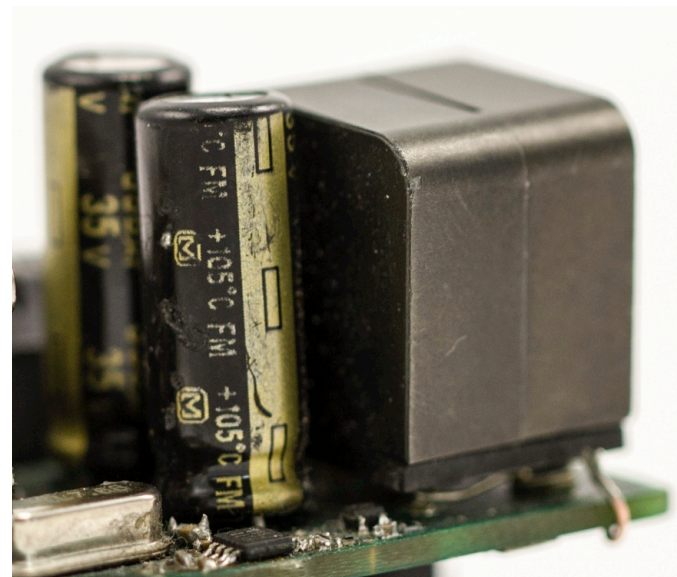


Si lateral power transistors

- “dual on die” electrically isolated super-junction lateral power transistors.
- 2 x 140 V, 1.2 Ω N-ch MOSFETs
- Using a 0.18 μm SOI process.

E-poster tomorrow!





Applications for PwrSoC
Enablers: semiconductors

Disablers: passive components

What's new on the architecture side?

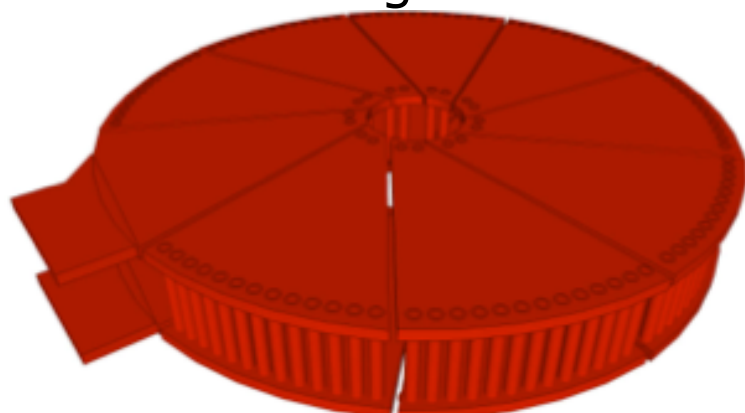
AGENDA

Passive components in PwrSoC

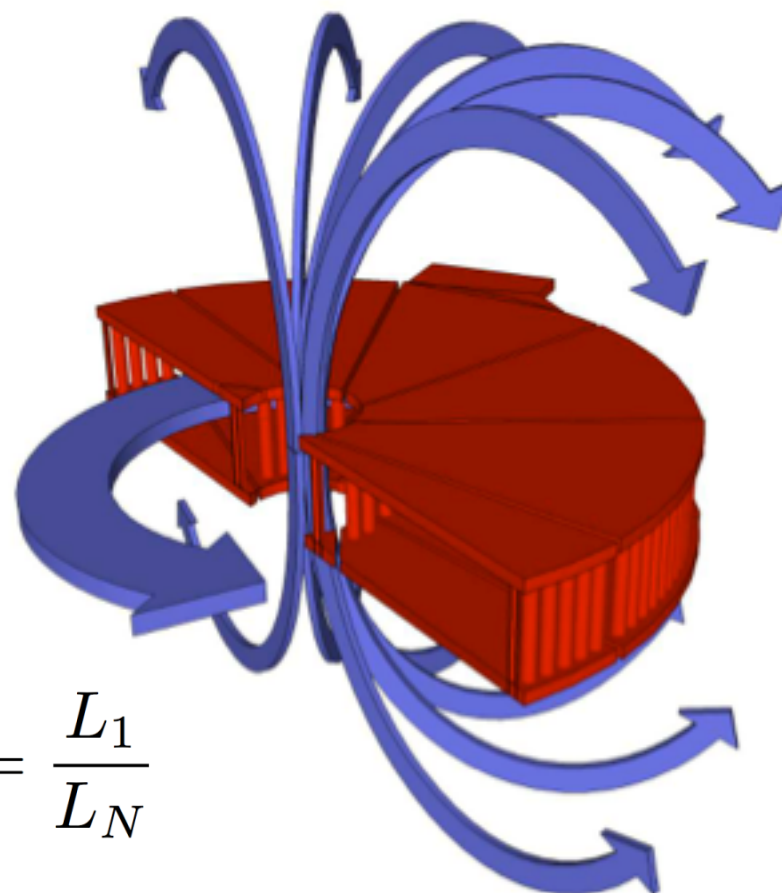
- PwrSoC:
 - lighter, cheaper, less material;
 - at mass production material amount is proportional to material cost
- so less material => less cost
- Therefore:
 - magnetic core manufacturers & capacitor manufacturers: Potentially losing turn-over
- Main focus on inductors here
- Academia: trying hard with new materials
 - some go air-core approach

PCB toroids

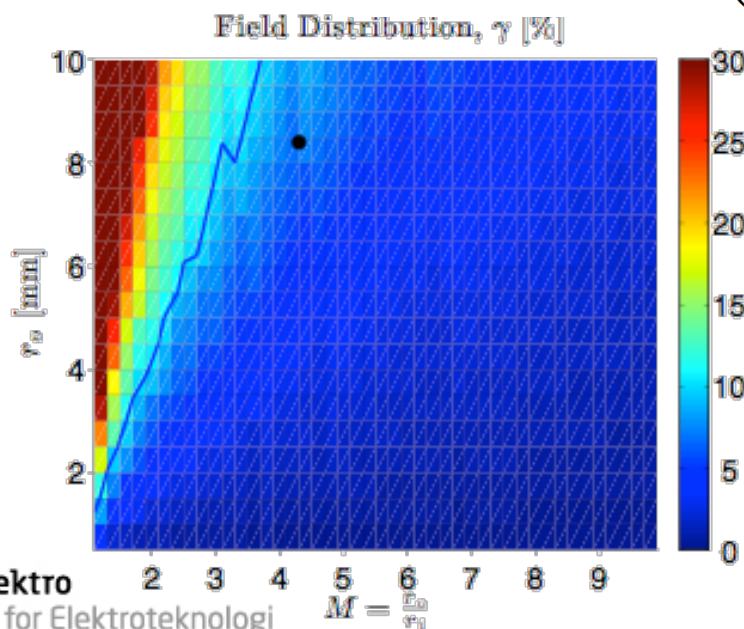
- Contained magnetic field



- Single turn field



- Field ratios $L_N = \frac{N^2 h \mu}{2\pi} \ln \left(\frac{r_o}{r_i} \right)$

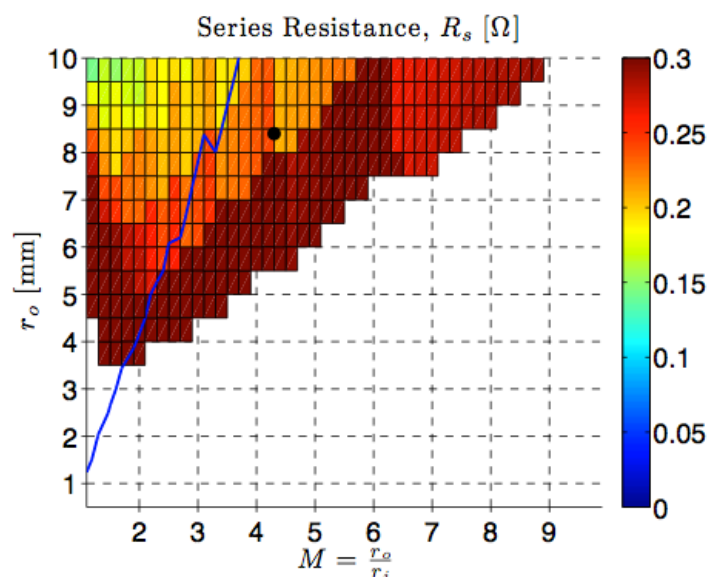
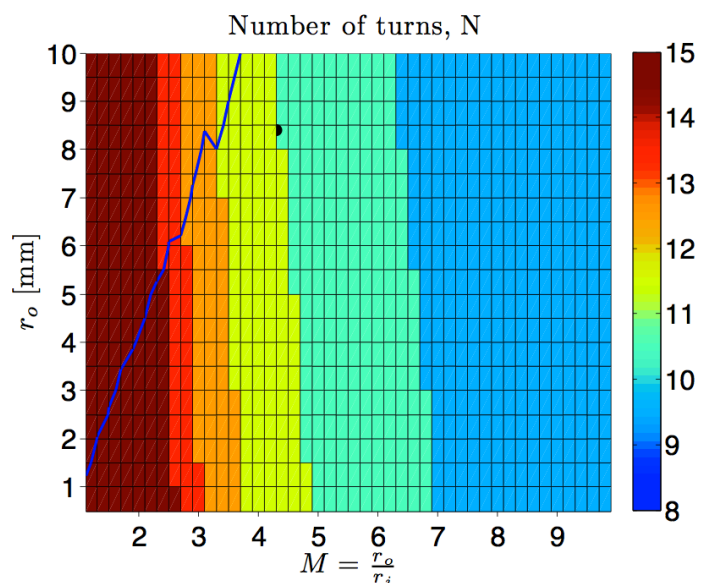


$$\gamma = \frac{L_1}{L_N}$$

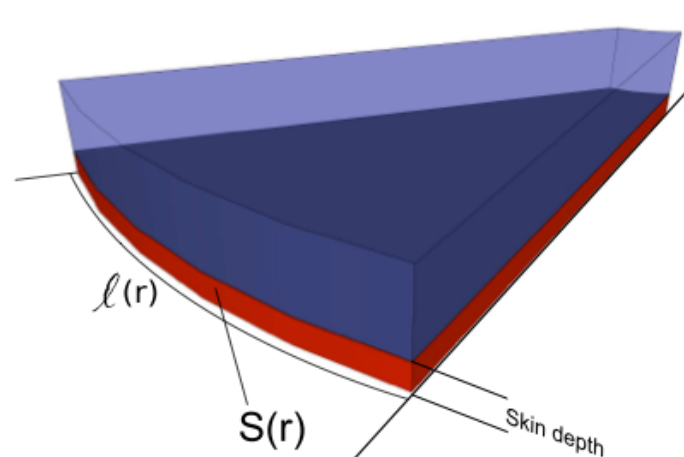
$$L_1 = \frac{r_i + r_o}{2} \mu \left[\ln \left(8 \frac{r_o + r_i}{r_o - r_i} \right) - 2 \right]$$

Design for inductance and losses

- N for 50 nH



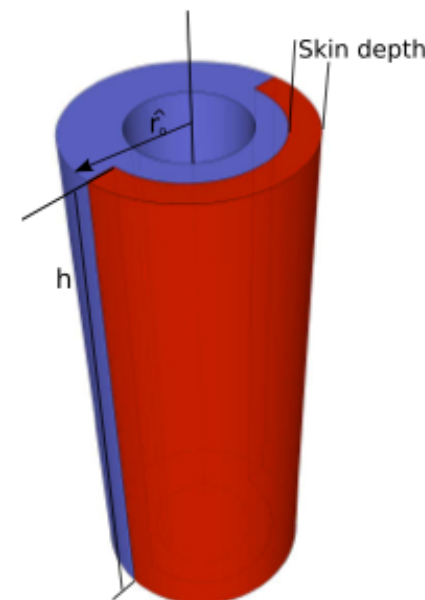
- Slab modelling



$$R_{\text{slab}} = \int_{r_i}^{r_o} \frac{r \rho}{\delta \left(\frac{2\pi}{N} r - \alpha \right)} dr$$

$$= \frac{\rho N}{2\pi \delta} \ln \left(\frac{2\pi r_o - \alpha N}{2\pi r_i - \alpha N} \right) \quad \forall 2\pi r_i > \alpha N$$

- Via modelling



$$R_{\text{via}} = \frac{h\rho}{S} = \frac{2h\rho}{\pi\delta(2\hat{r}_o - \delta)}$$

- Total resistance per turn

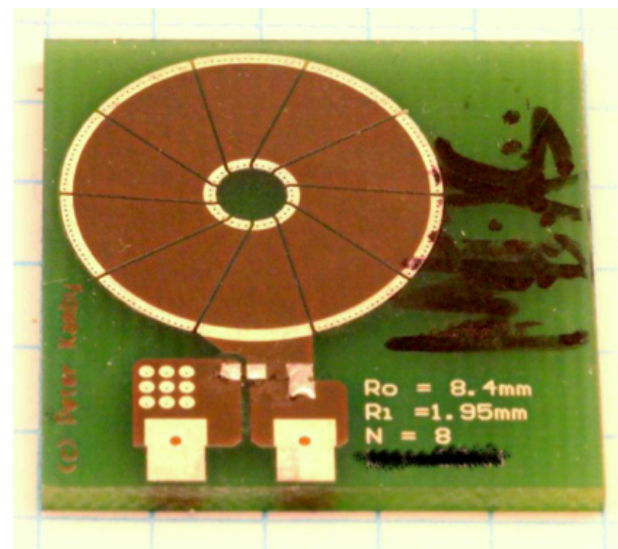
$$R'_w = 2R_{\text{slab}} + \frac{R_{\text{via}}}{n_i} + \frac{R_{\text{via}}}{n_o}$$

$$= \frac{\rho N}{\pi \delta} \ln \left(\frac{2\pi r_o - \alpha N}{2\pi r_i - \alpha N} \right) + \frac{2h\rho(n_i + n_o)}{\pi\delta(2\hat{r}_o - \delta)n_i n_o}$$

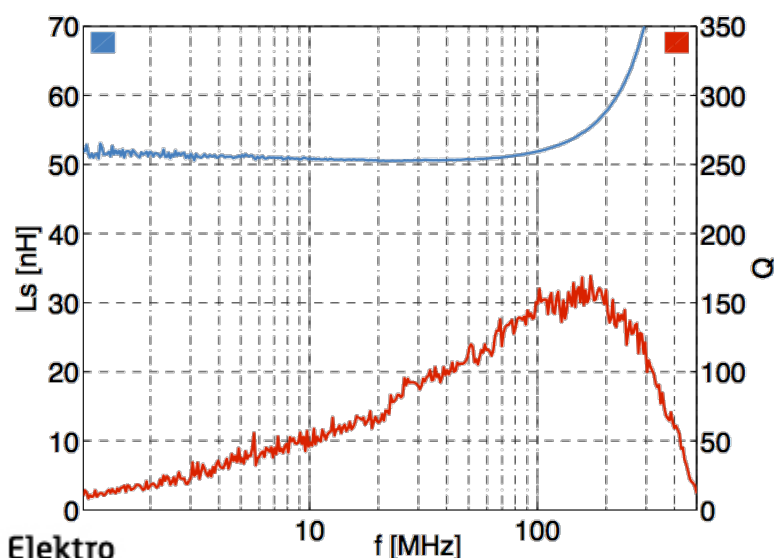
Experimental verification

• specification

Parameter	50 nH inductor
Inductance L	50.3 nH
Outer radius r_o	8.4 mm
Radius ratio M	4.3
Inner radius r_i	≈ 1.95 mm
Toroid height h	1.6 mm
Number of turns N	8
Resulting total resistance R	209 m Ω
Field distribution factor γ	7.7 %



• measurement



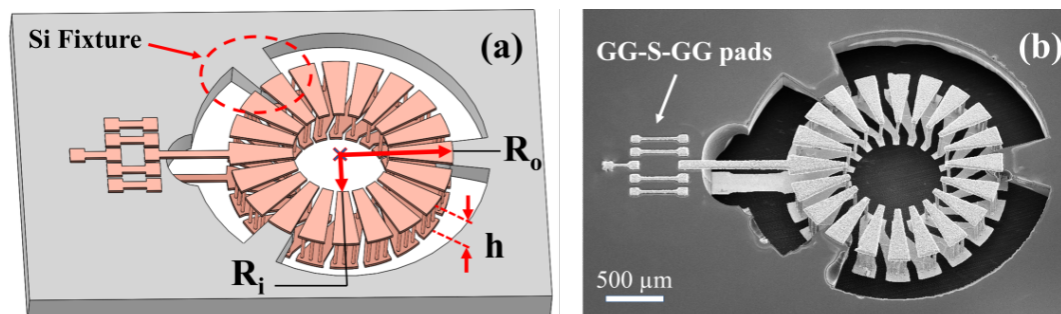
• verification

	Design	Calculation	Measurement
Inductance L	50 nH	50.3 nH	52 nH
Series resistance R	—	209 m Ω	219 m Ω
Quality factor Q	—	151	149

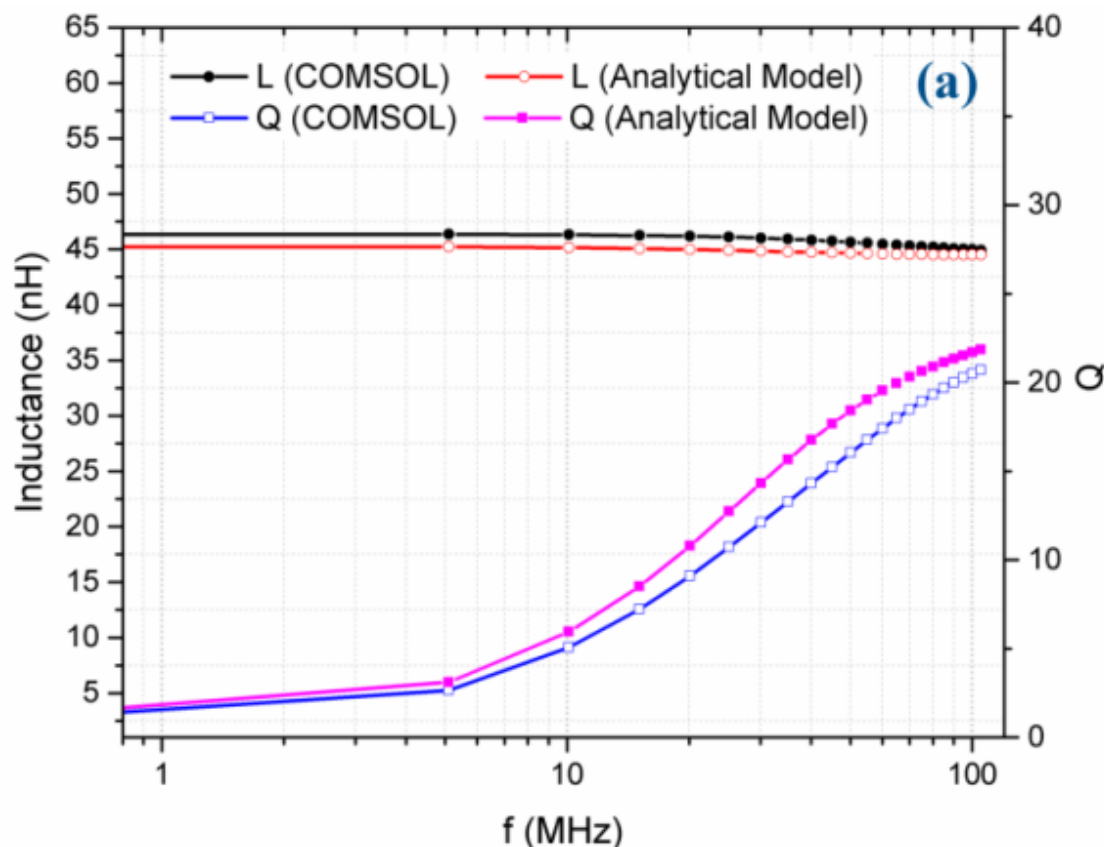
"Printed Circuit Board Integrated Toroidal Radio Frequency Inductors", Kamby, P.; Knott, A. ; Andersen, M.A.E., *IEEE Industrial Electronics Conference (IECON)*, October 2012

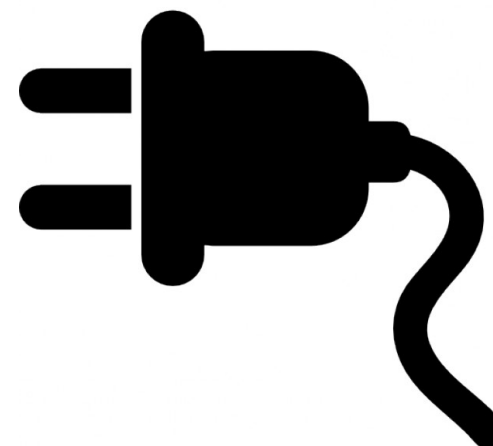
Integrated air core toroid

- $L = 45 \text{ nH}$
- $Q_{pk} = 21$
- $A = 4 \text{ mm}^2$
- More to come at APEC!



E-poster tomorrow!





Applications for PwrSoC
Enablers: semiconductors
Disablers: passive components

What's new on the architecture side?

AGENDA

Architectures

- AC/DC interface
 - Rectifiers
 - Power combiner through switched cap
 - Ripple ports
 - Inductive based
 - Switched cap
- DC/DC through Very High Frequency (VHF, 30 MHz – 300 MHz)
 - Class E, Class Φ_2 , Class DE
 - Stacking

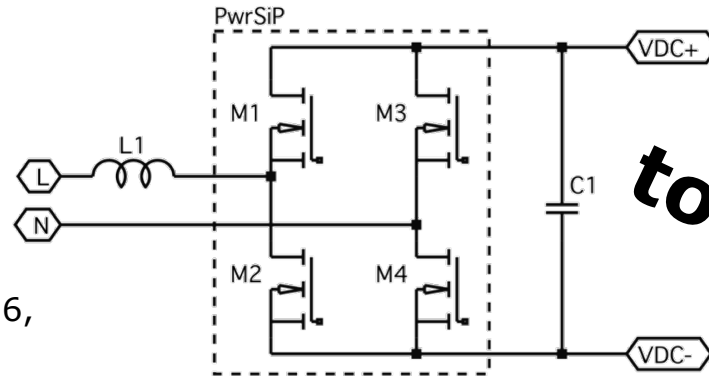
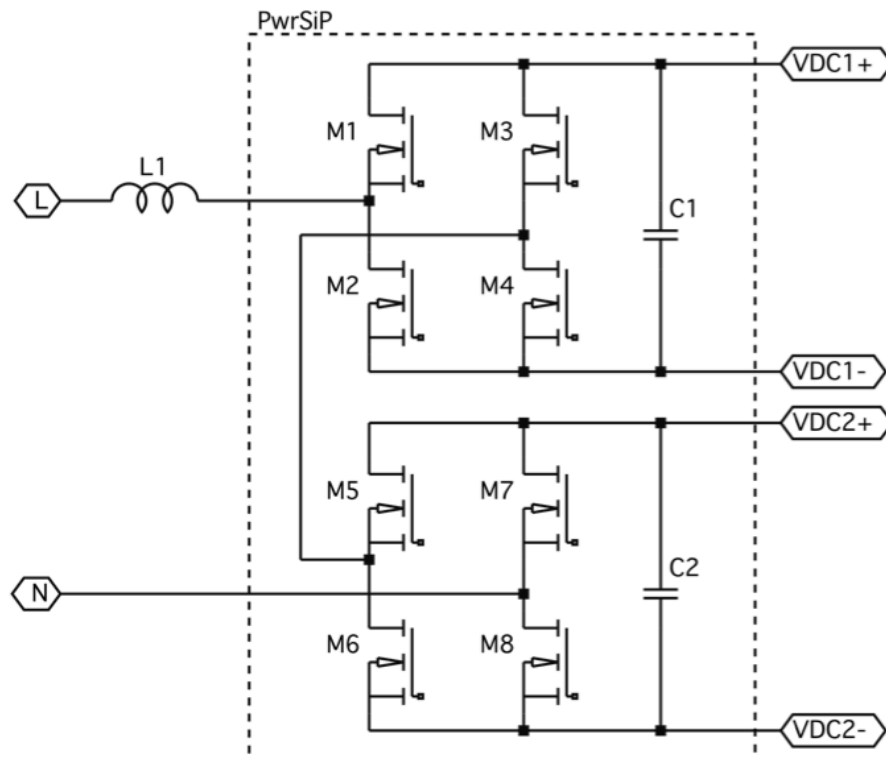
Rectifiers

- Bridgeless Totem Pole

(Infineon, "GaN in a Silicon world: competition or coexistence", APEC 2016, Industry Presentation, slide 17)

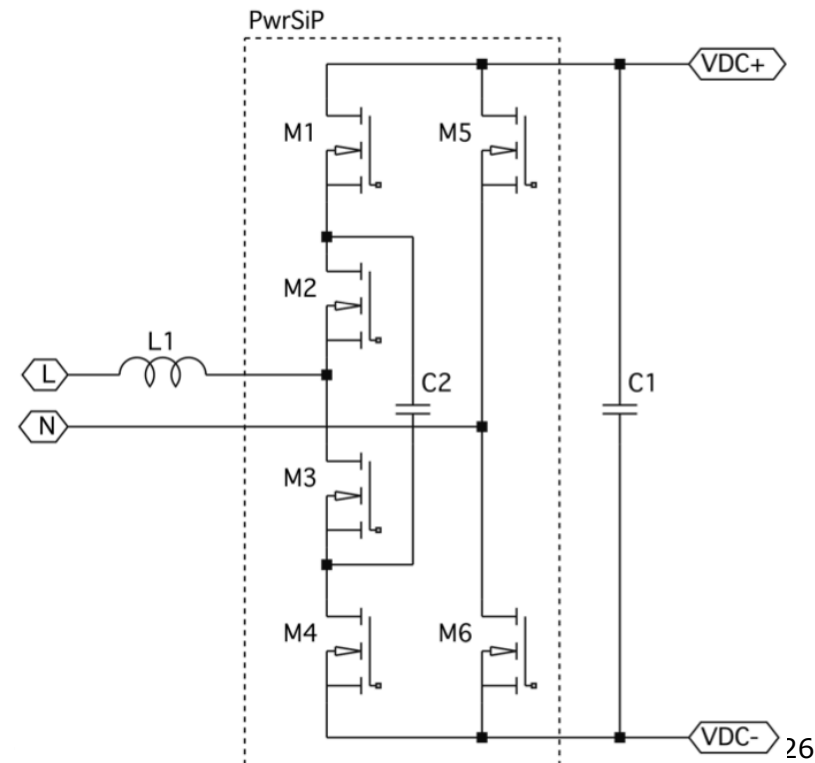
- Cascaded multi-cell rectifier

(Kasper, M., et al. "Hardware verification of a hyper-efficient (98%) and super-compact (2.2 kW/dm³) isolated AC/DC telecom power supply module based on multi-cell converter approach." APEC 2015)



- Bridgeless Totem Pole Rectifier with Flying Capacitor

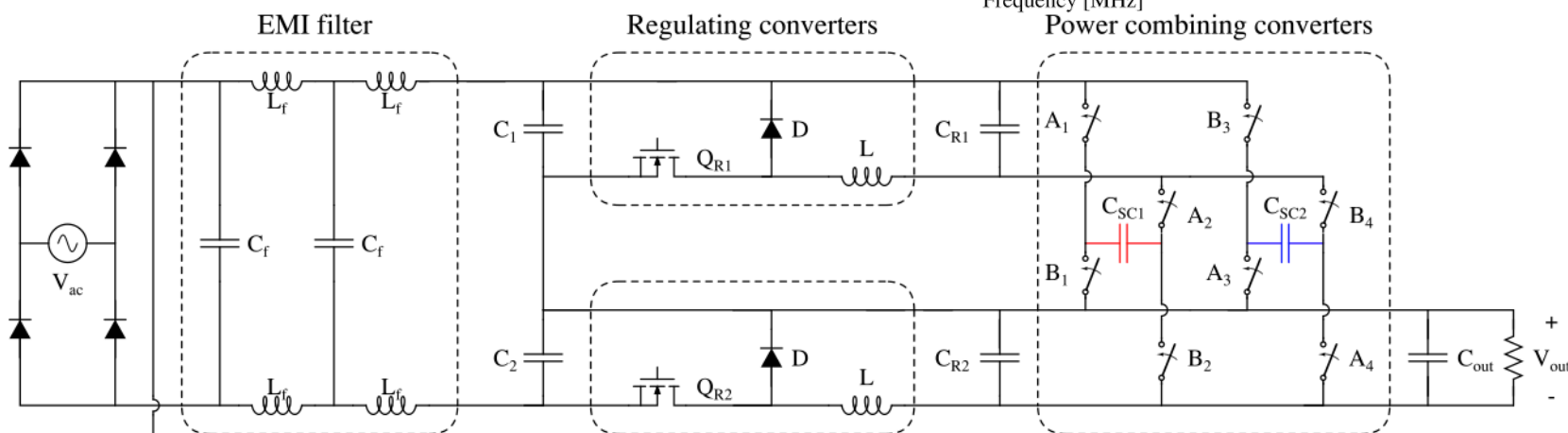
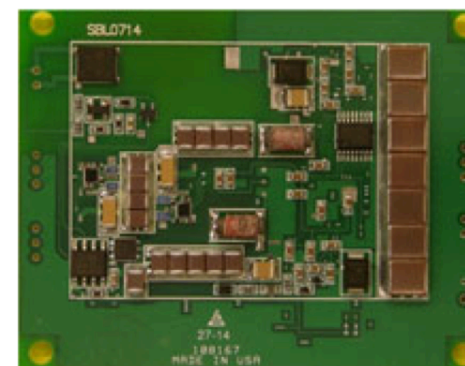
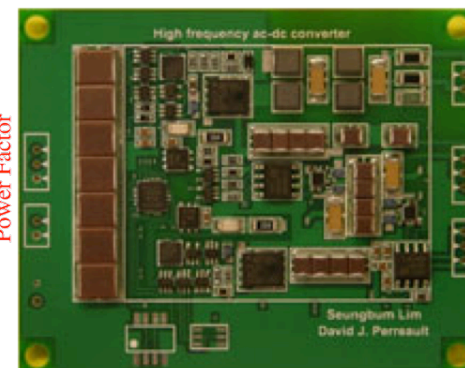
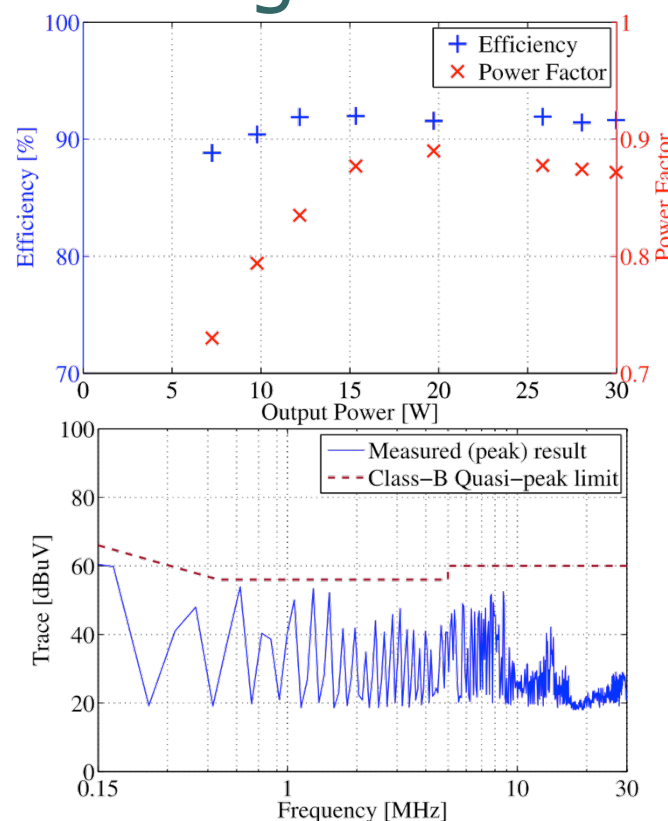
(Vu, T., et. al, "Implementation of multi-level bridgeless PFC rectifiers for mid-power single phase applications." APEC 2016)



Power combiner through switched cap

- US mains \rightarrow 35 V
- $f_{sw} = 3 - 10$ MHz
- $\eta_{peak} = 92\%$
- $PF = 0,89$
- $P/Vol = 3,1$ W/cm³

(Lim, S., et. al, "New AC-DC Power Factor Correction Architecture Suitable for High-Frequency Operation." *IEEE Transactions on Power Electronics* 31.4 (2016).)

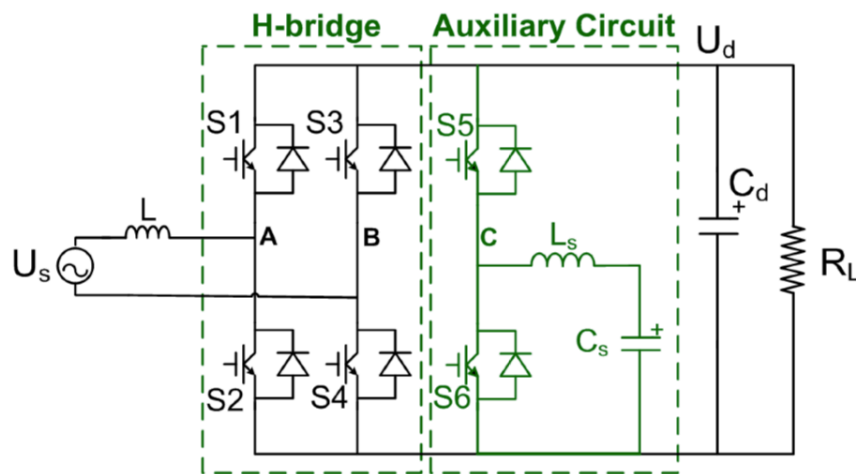
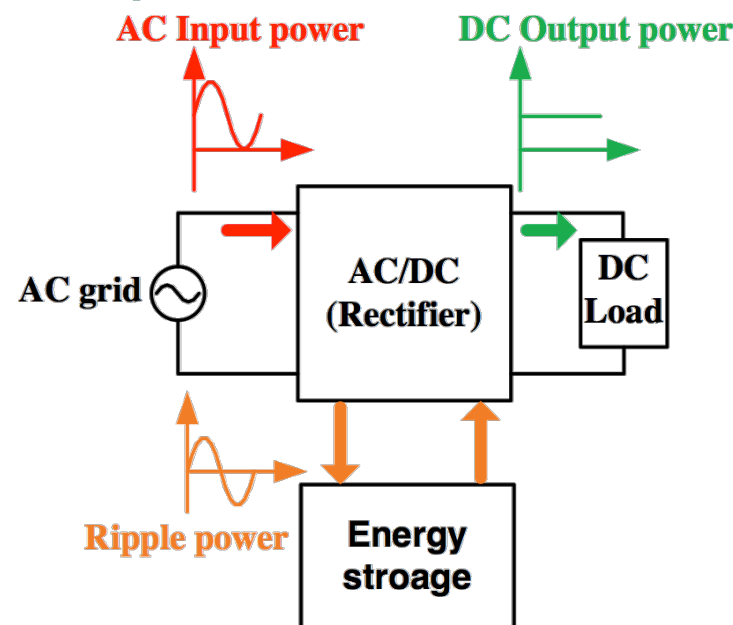


Inductive-based ripple port

- US-mains -> 42 V
- Output ripple:
 $5 \% * V_{out}$

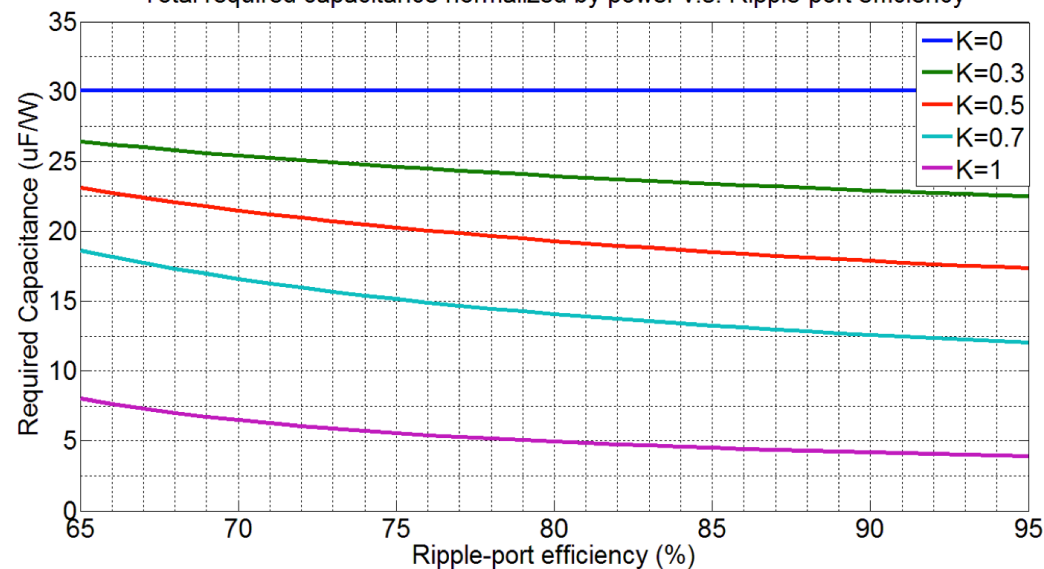
(Wang, R., et al. "A high power density singlephase PWM rectifier with active ripple energy storage." *APEC 2010*.)

(Tian, B., *A Single-phase Rectifier With Ripple-power Decoupling and Application to LED Lighting*. M.Sc. thesis. Texas A&M University, 2015.)

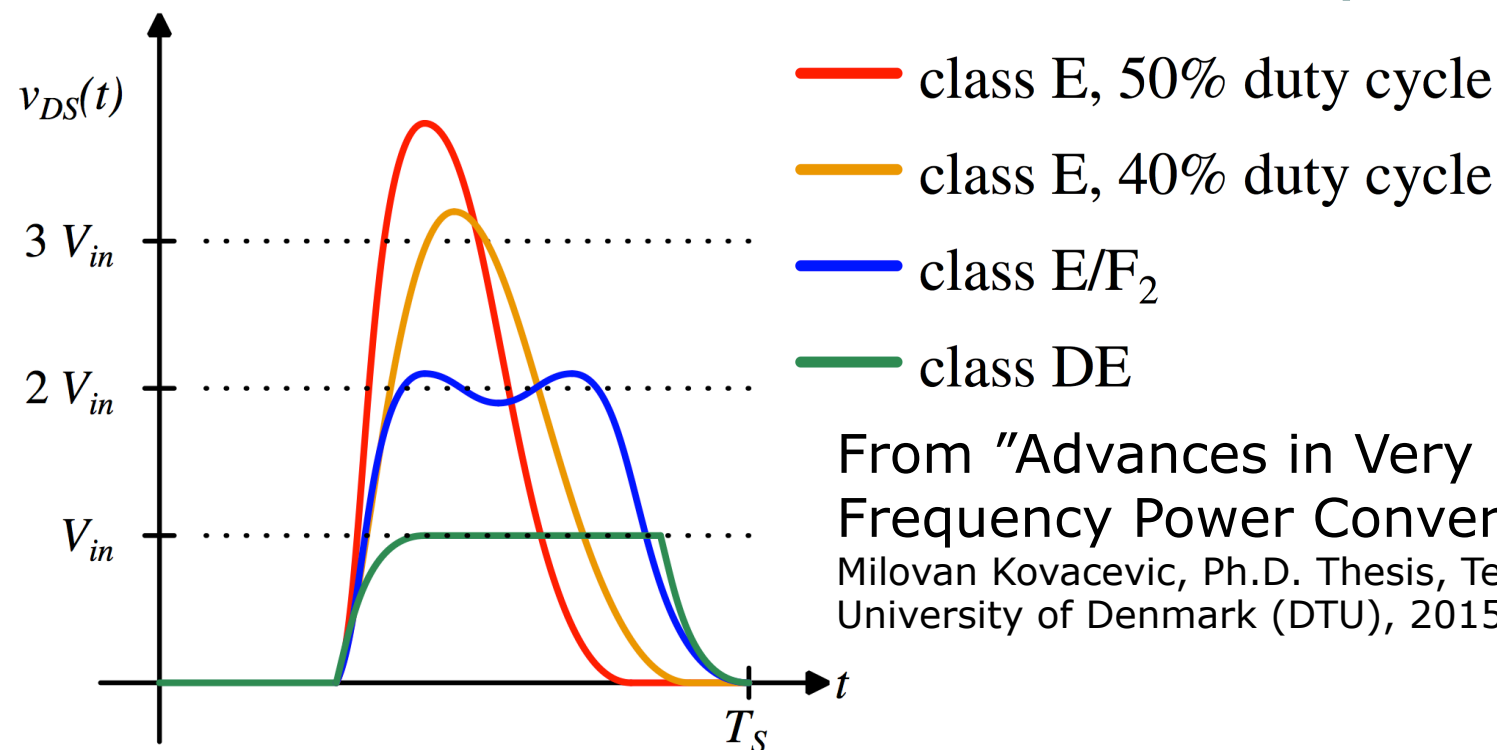


$$K = \frac{P_{rpp_ripple}}{P_{LED} + P_{rpp_loss}}$$

Total required capacitance normalized by power v.s. Ripple-port efficiency



VHF DC-DC resonant converter topologies



From "Advances in Very High Frequency Power Conversion",
 Milovan Kovacevic, Ph.D. Thesis, Technical
 University of Denmark (DTU), 2015

High voltages

⇒ bigger distances on
semiconductor die

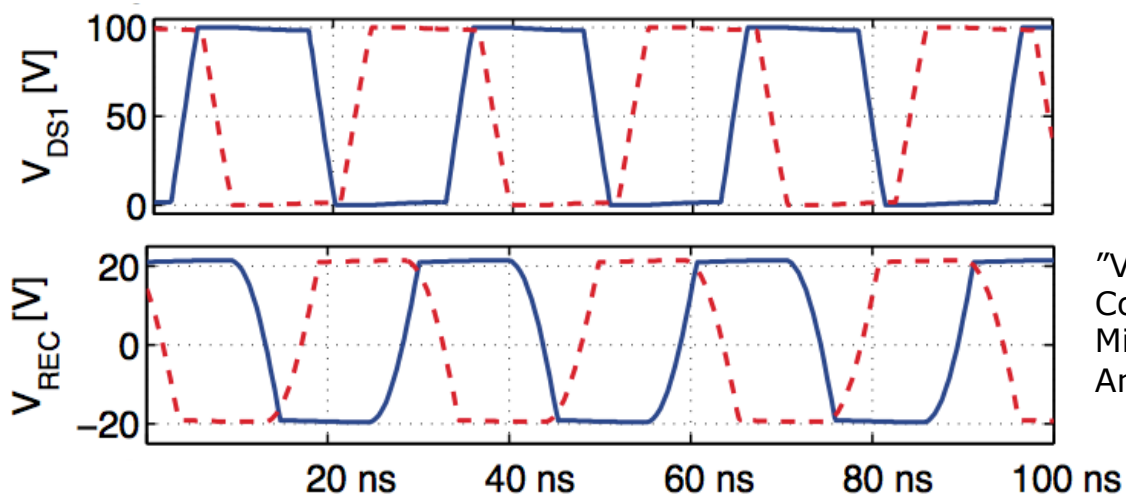
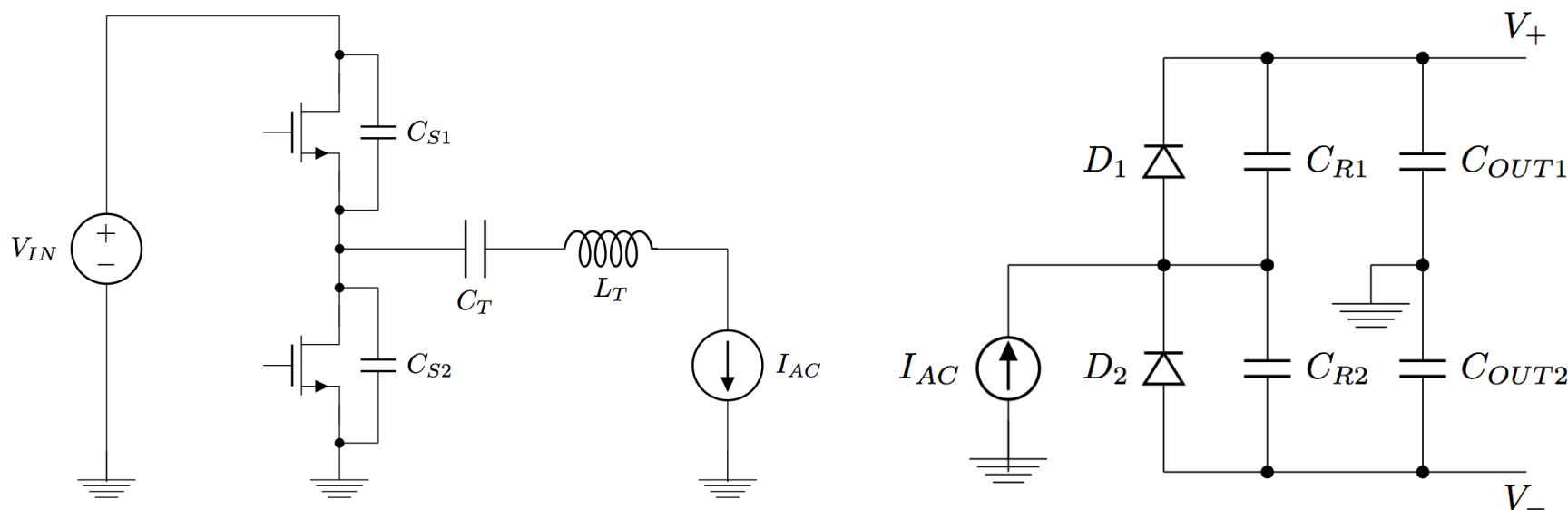
⇒ therefore bigger parasitic "plates"

⇒ Bigger capacitances

BUT:
$$f_{max} = \frac{P_o}{2\pi^2 C_{oss} V_i^2}$$

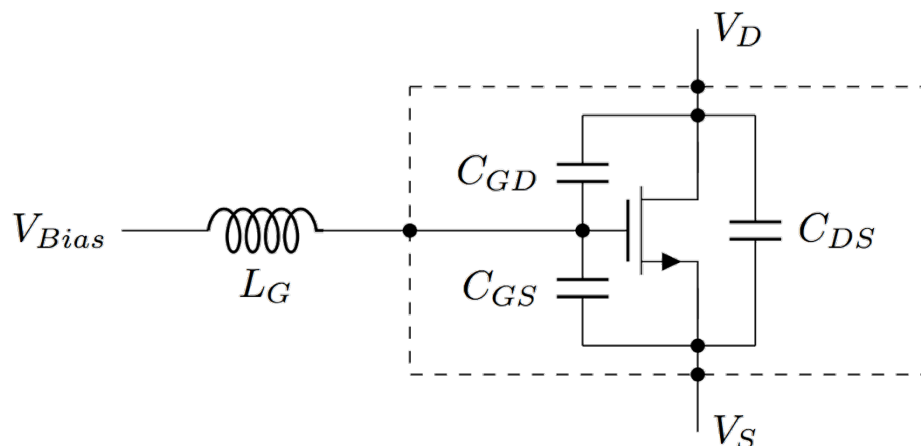
"Radio Frequency Switch Mode Power Supplies",
 Toke M. Andersen, MSc. Thesis, Technical University
 of Denmark (DTU), 2010

Class-DE is reducing voltage stress

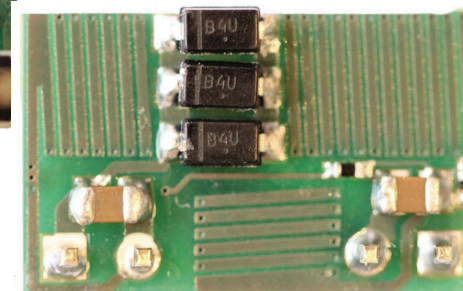
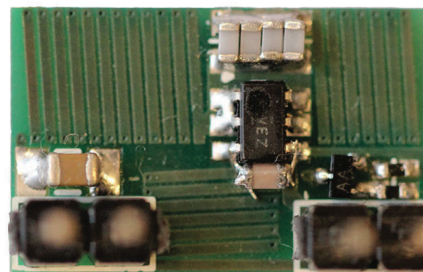
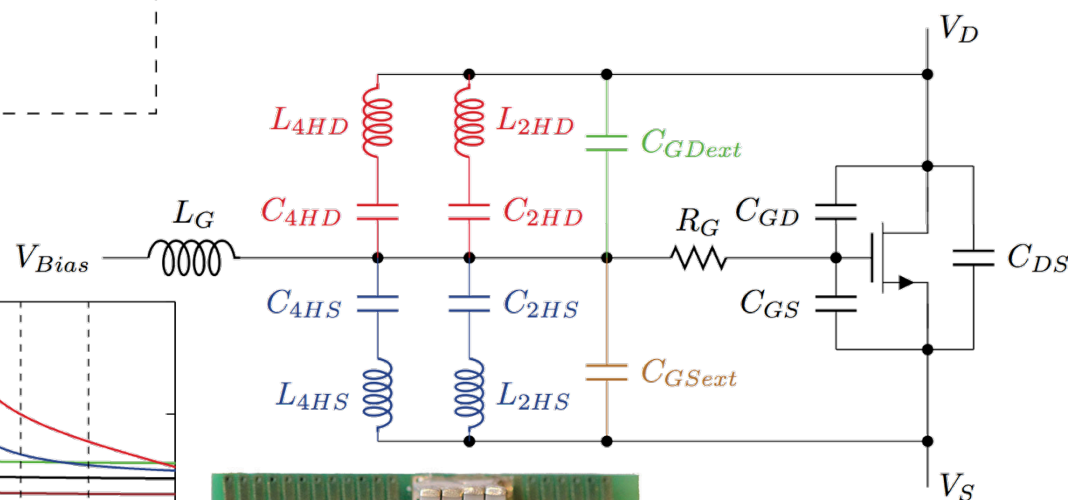
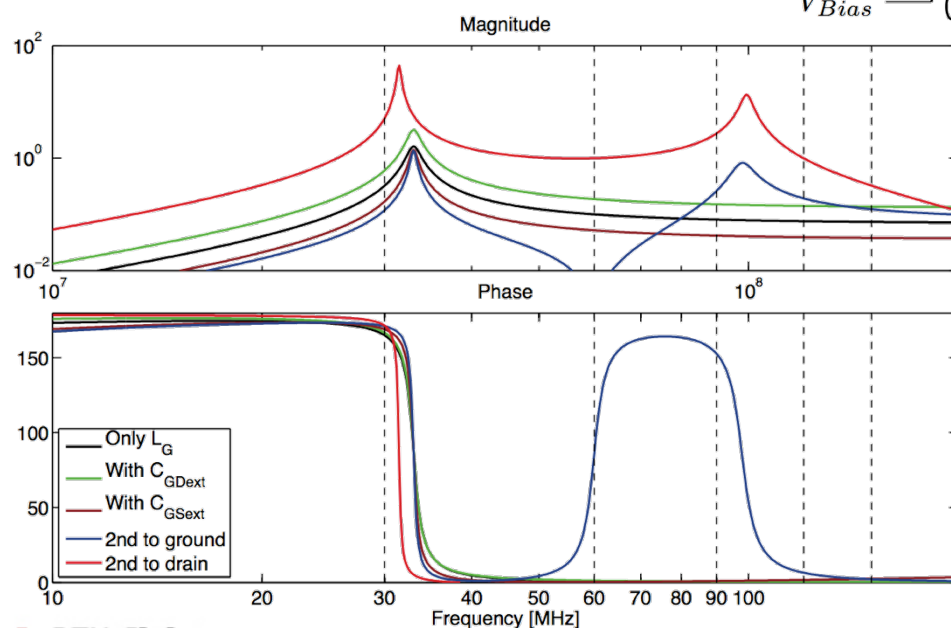


"Very High Frequency Half Bridge DC/DC Converter",
Mickey P. Madsen, Arnold Knott, Michael A.E. Andersen, APEC 2014

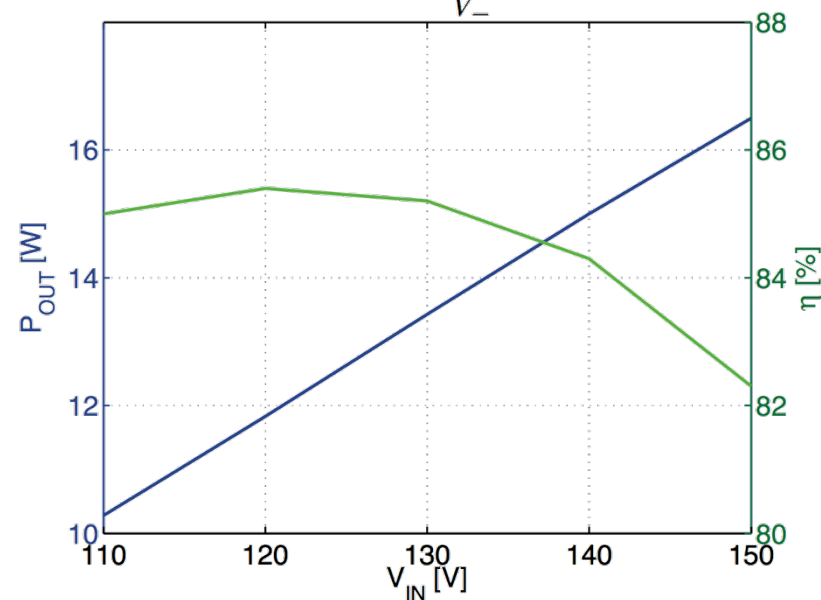
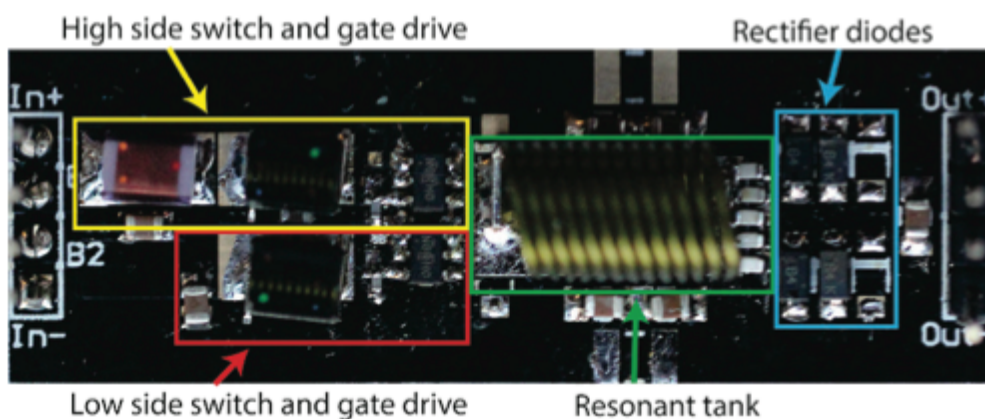
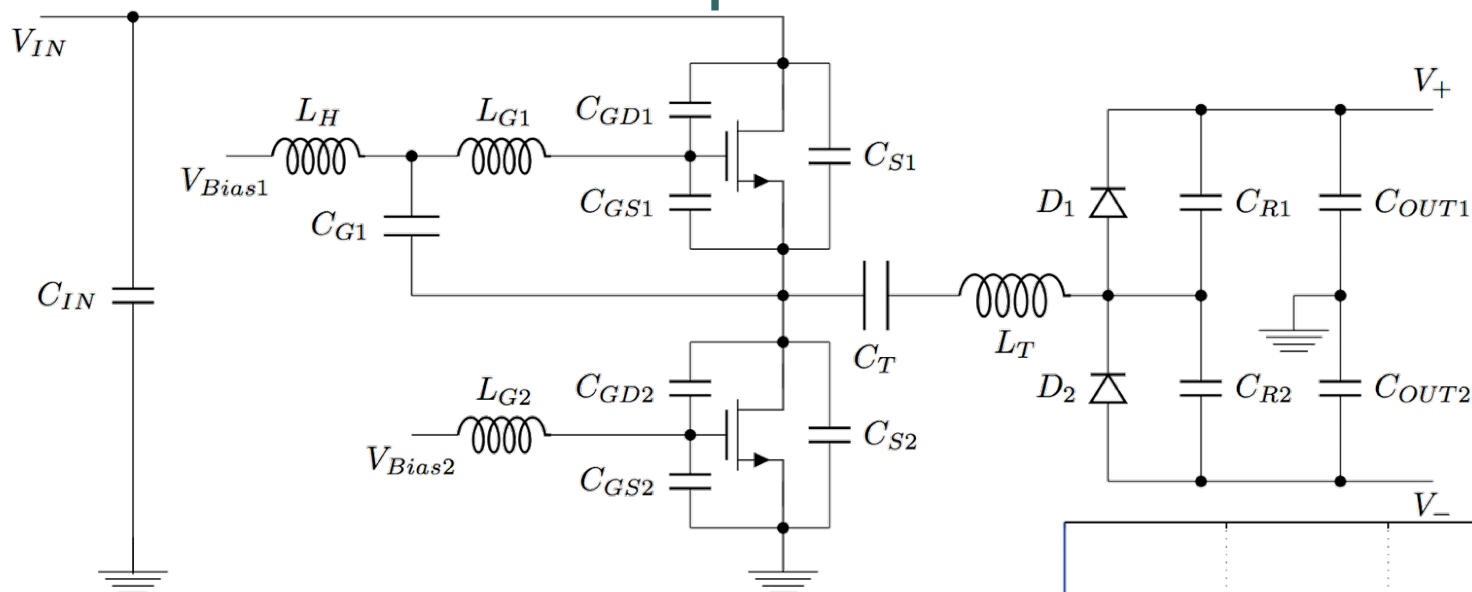
Gate Drive is the key



"Self-Oscillating Resonant Gate Drive for Resonant Inverters and Rectifiers Composed Solely of Passive Components", Mickey P. Madsen, Jeppe A. Pedersen, Arnold Knott, Michael A. E. Andersen, APEC 2014



Class-DE final implementation

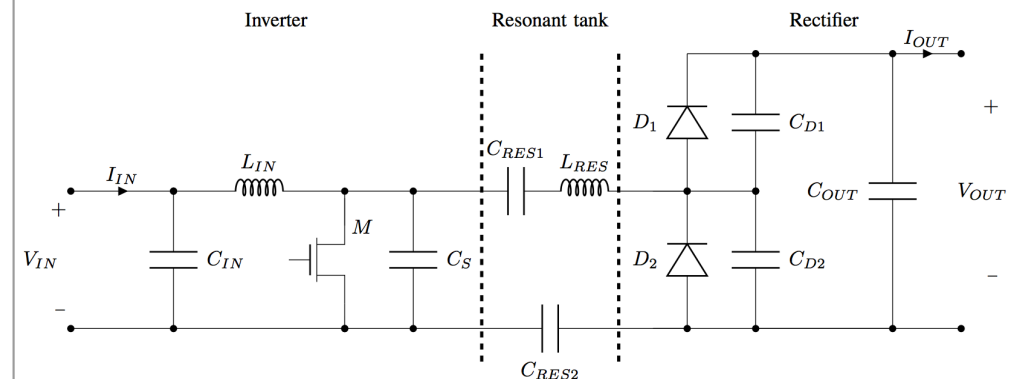
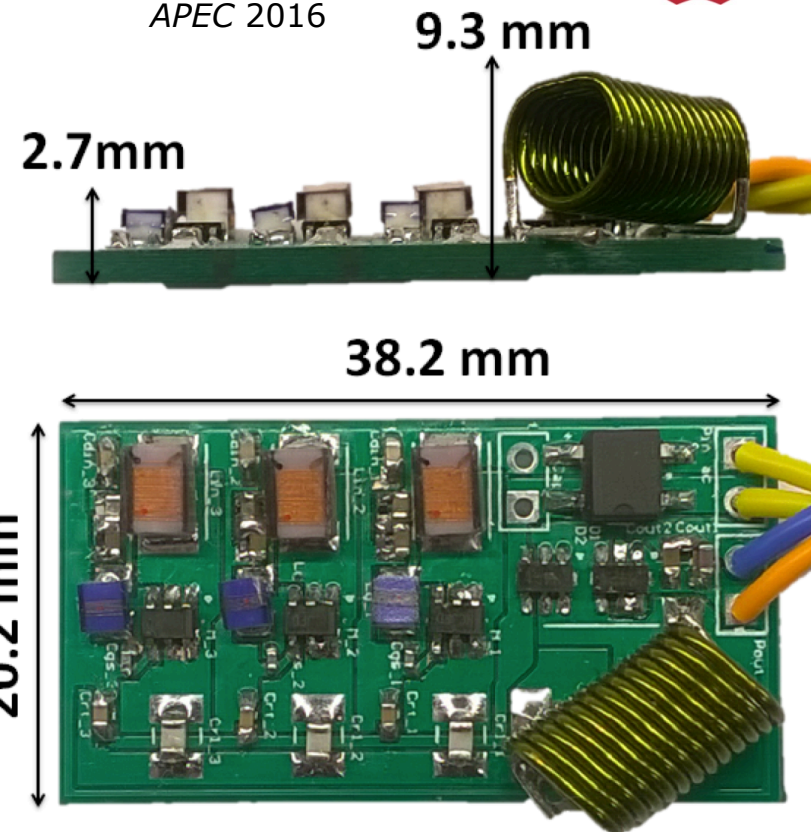
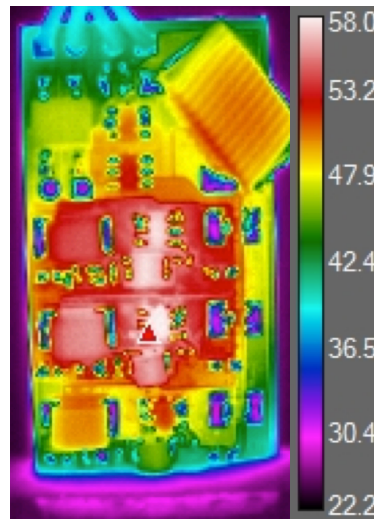
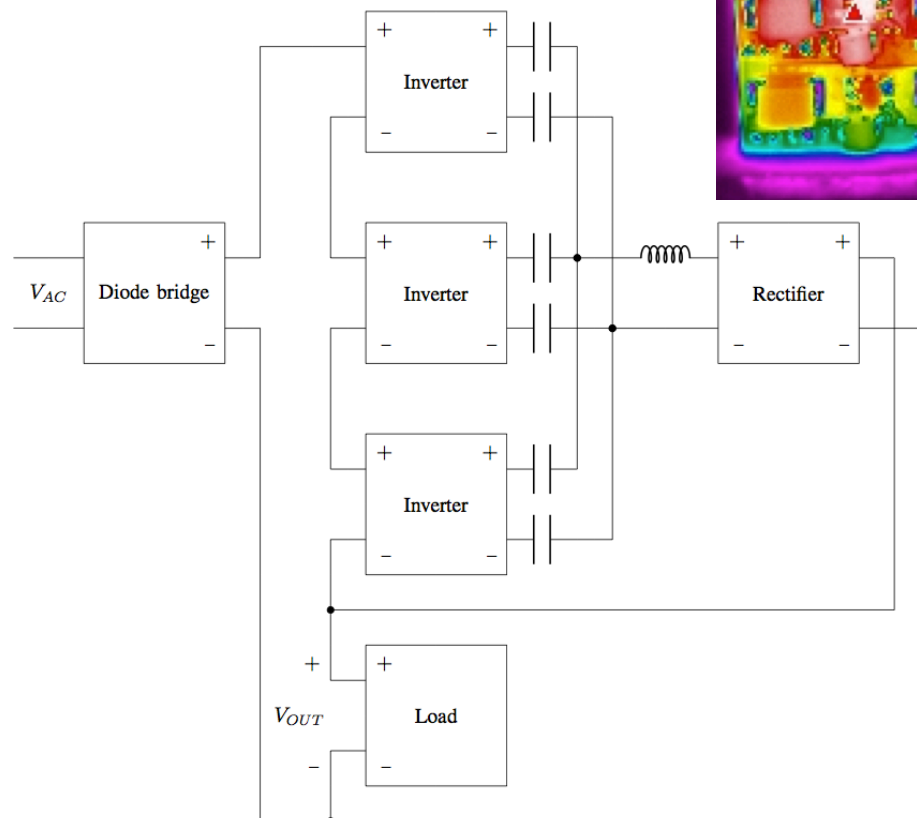


"Very High Frequency Half Bridge DC/DC Converter",
Mickey P. Madsen, Arnold Knott, Michael A.E. Andersen, APEC 2014

Stacking of VHF converters

- US mains -> 60 V LED
- $f_{sw} = 37 \text{ MHz}$
- $\eta_{peak} = 89,4 \%$
- $P/Vol = 2,1 \text{ W/cm}^3$

Pedersen, Jeppe A., et al. "US mains stacked Very High Frequency self-oscillating resonant power converter with unified rectifier." DTU APEC 2016



Conclusion on components

- PwrSoC:
 - smaller, lighter, less material (for passives) => cheaper
- Smaller passives (material volume ~ mass production cost):
 - magnetic core manufacturers & capacitor manufacturers:
Potentially loosing turn-over
 - Unless we find new markets / applications,
like LED drivers
- Bigger part of the cake goes to semiconductor companies
- Academia: trying hard with new materials,
some go air-core approach

Conclusion on architectures

- Intensified research on AC/DC
 - mains interface
 - Ripple ports
- Intensified research on DC/AC
 - see google little box challenge
- Stacking in DC/DC
 - Galvanic isolation solutions found
 - Enables stacking for both inductor based and switched cap approaches

**THANK YOU FOR THE
INVITATION AND YOUR
INTEREST!
PLEASE VISIT OUR E-
POSTERS FROM**

**HOA THANH
J. CHRISTIAN HERTEL
JENS PEJTERSEN
LIN FAN
YASSER NOUR**